US00D505924S

(12) **United States Design Patent**
Okuyama et al.

(10) **Patent No.:** **US D505,924 S**
(45) **Date of Patent:** ** **Jun. 7, 2005**

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(54) **SEMICONDUCTOR ELEMENT**

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(73) Assignee: **Sony Corporation**, Tokyo (JP)

(**) Term: **14 Years**

(21) Appl. No.: **29/193,675**

(22) Filed: **Nov. 13, 2003**

(51) **LOC (8) Cl.** **13-03**
(52) **U.S. Cl.** **D13/182**
(58) **Field of Search** D13/182; D3/5; D21/834; 216/2, 11; 257/77, 94, 95, 190; 313/309, 311; 369/126; 438/20, 116; 455/50

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Assistant Examiner—Selina Sikder
(74) *Attorney, Agent, or Firm*—Rader, Fishman & Grauer PLLC

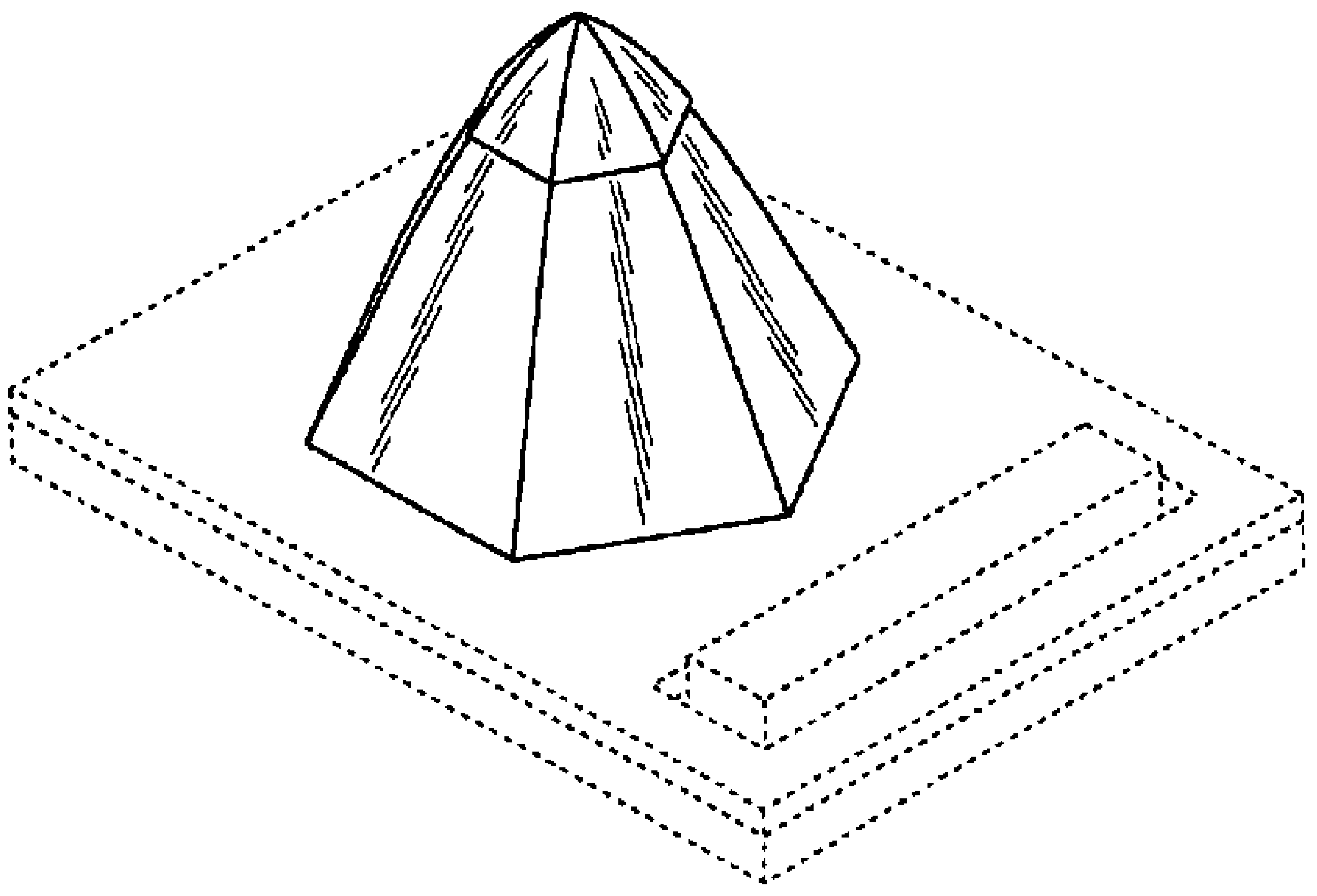
(57) **CLAIM**

The ornamental design for a semiconductor element, as shown and described.

DESCRIPTION

FIG. **1** is a perspective view of a first embodiment of a semiconductor element showing our new design;
FIG. **2** is a front elevational view thereof;
FIG. **3** is a rear elevational view thereof;
FIG. **4** is a left side elevational view thereof;
FIG. **5** is a right side elevational view thereof; and
FIG. **6** is a top plan view thereof.
FIG. **7** is a perspective view of a second embodiment of a semiconductor element showing our new design;
FIG. **8** is a front elevational view thereof;
FIG. **9** is a rear elevational view thereof;
FIG. **10** is a left side elevational view thereof;
FIG. **11** is a right side elevational view thereof; and
FIG. **12** is a top plan view thereof.
FIG. **13** is a perspective view of a third embodiment of a semiconductor element showing our new design;
FIG. **14** is a front elevational view thereof;
FIG. **15** is a rear elevational view thereof;
FIG. **16** is a left side elevational view thereof;
FIG. **17** is a right side elevational view thereof; and
FIG. **18** is a top plan view thereof.
FIG. **19** is a perspective view of a fourth embodiment of a semiconductor element showing our new design;
FIG. **20** is a front elevational view thereof;
FIG. **21** is a rear elevational view thereof;
FIG. **22** is a left side elevational view thereof;
FIG. **23** is a right side elevational view thereof; and
FIG. **24** is a top plan view thereof.
Lower part of the semiconductor element is opaque or transparent.
FIG. **25** is a perspective view of a fifth embodiment of a semiconductor element showing our new design;
FIG. **26** is a front elevational view thereof;
FIG. **27** is a rear elevational view thereof;
FIG. **28** is a left side elevational view thereof;
FIG. **29** is a right side elevational view thereof; and
FIG. **30** is a top plan view thereof.
Lower part of the semiconductor element is opaque or transparent.
FIG. **31** is a perspective view of a sixth embodiment of a semiconductor element showing our new design;
FIG. **32** is a front elevational view thereof;
FIG. **33** is a rear elevational view thereof;
FIG. **34** is a left side elevational view thereof;
FIG. **35** is a right side elevational view thereof; and,
FIG. **36** is a top plan view thereof.
Lower part of the semiconductor element is opaque or transparent.
The broken lines shown in the Figures are for illustrative purposes only and form no part of the claimed design. A bottom plan view in the first, second, third, fourth, fifth, and sixth embodiments is not part of the claimed design.

1 Claim, 24 Drawing Sheets



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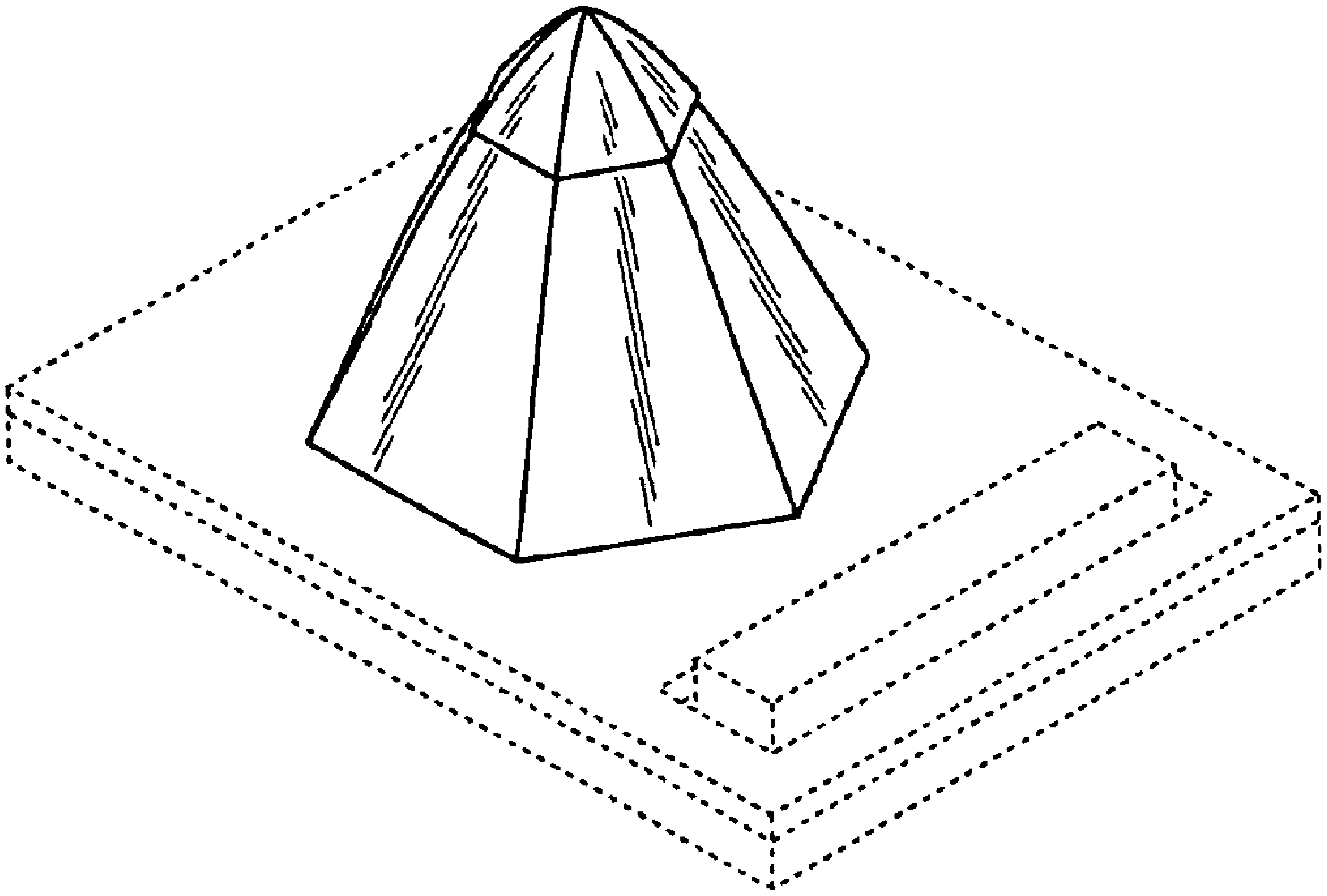


FIG. 1

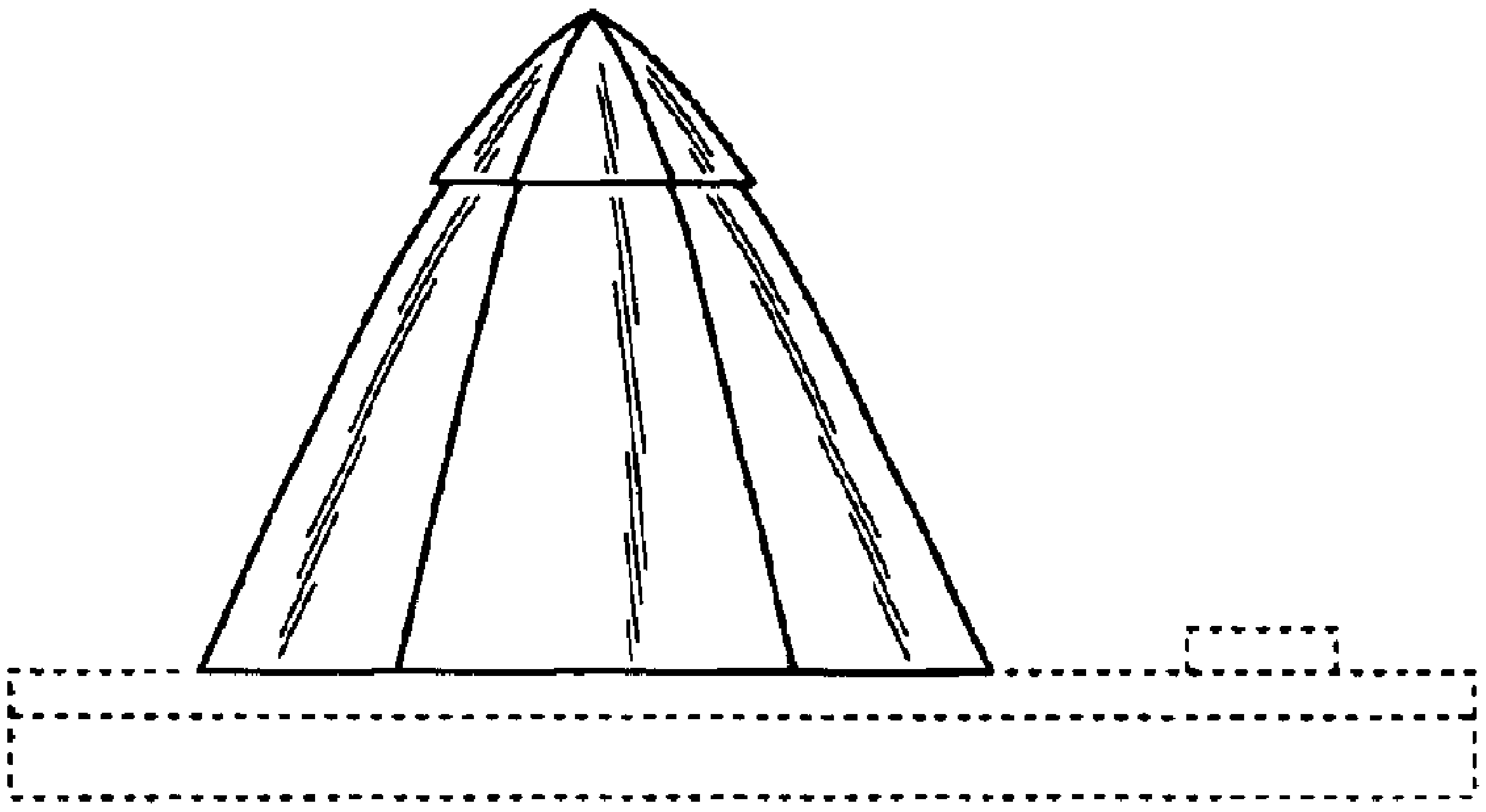


FIG. 2

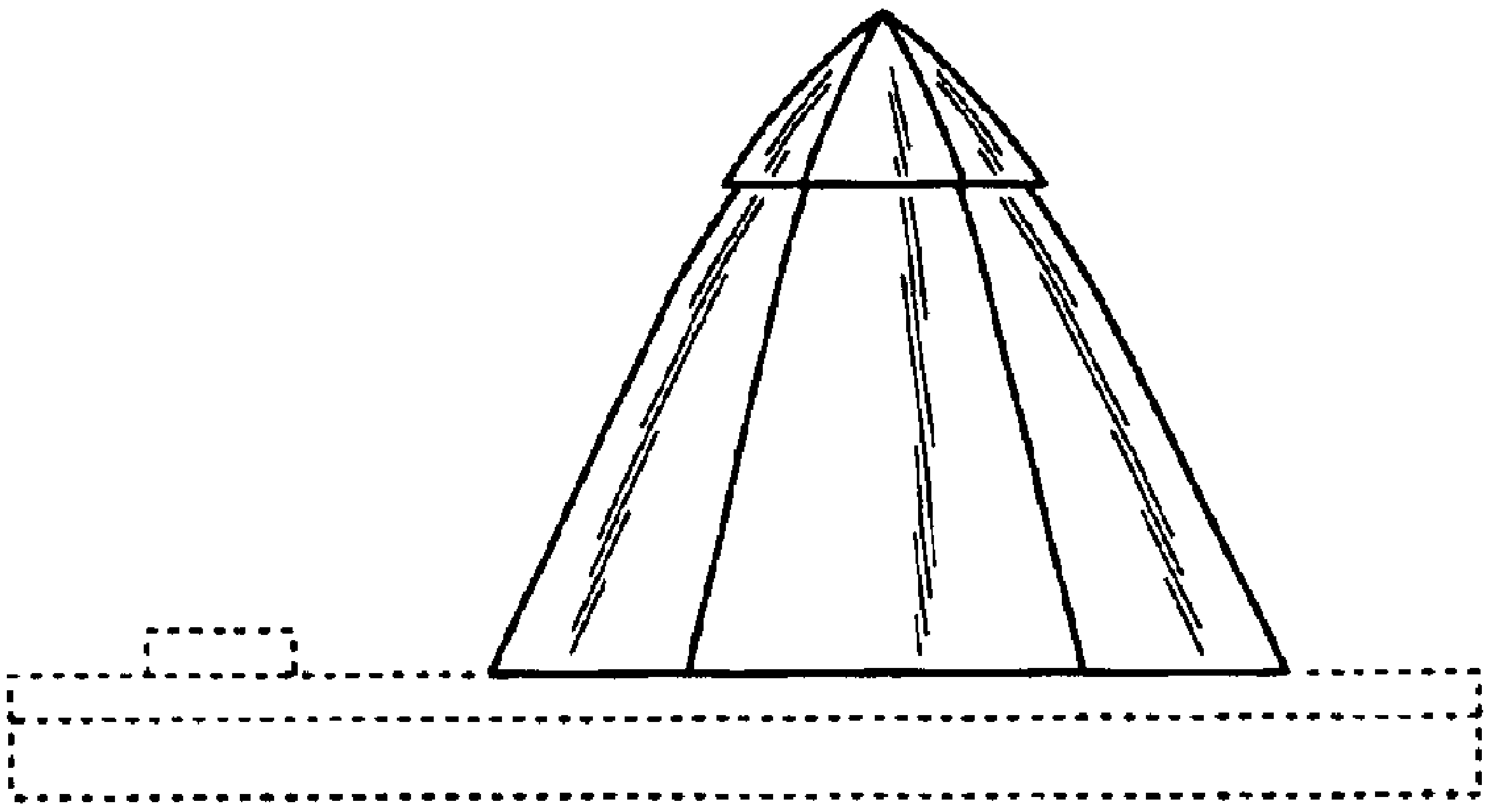


FIG. 3

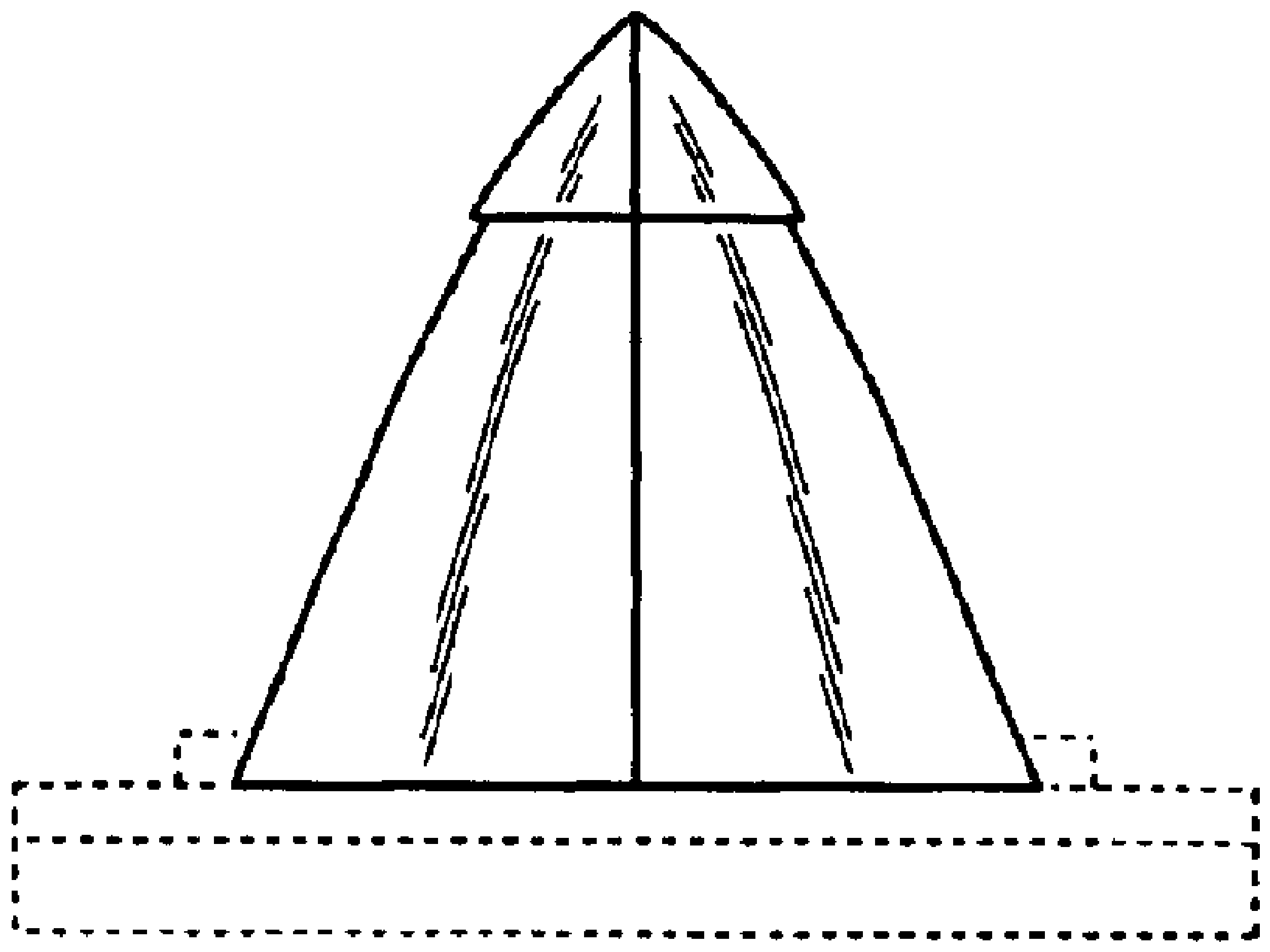


FIG. 4

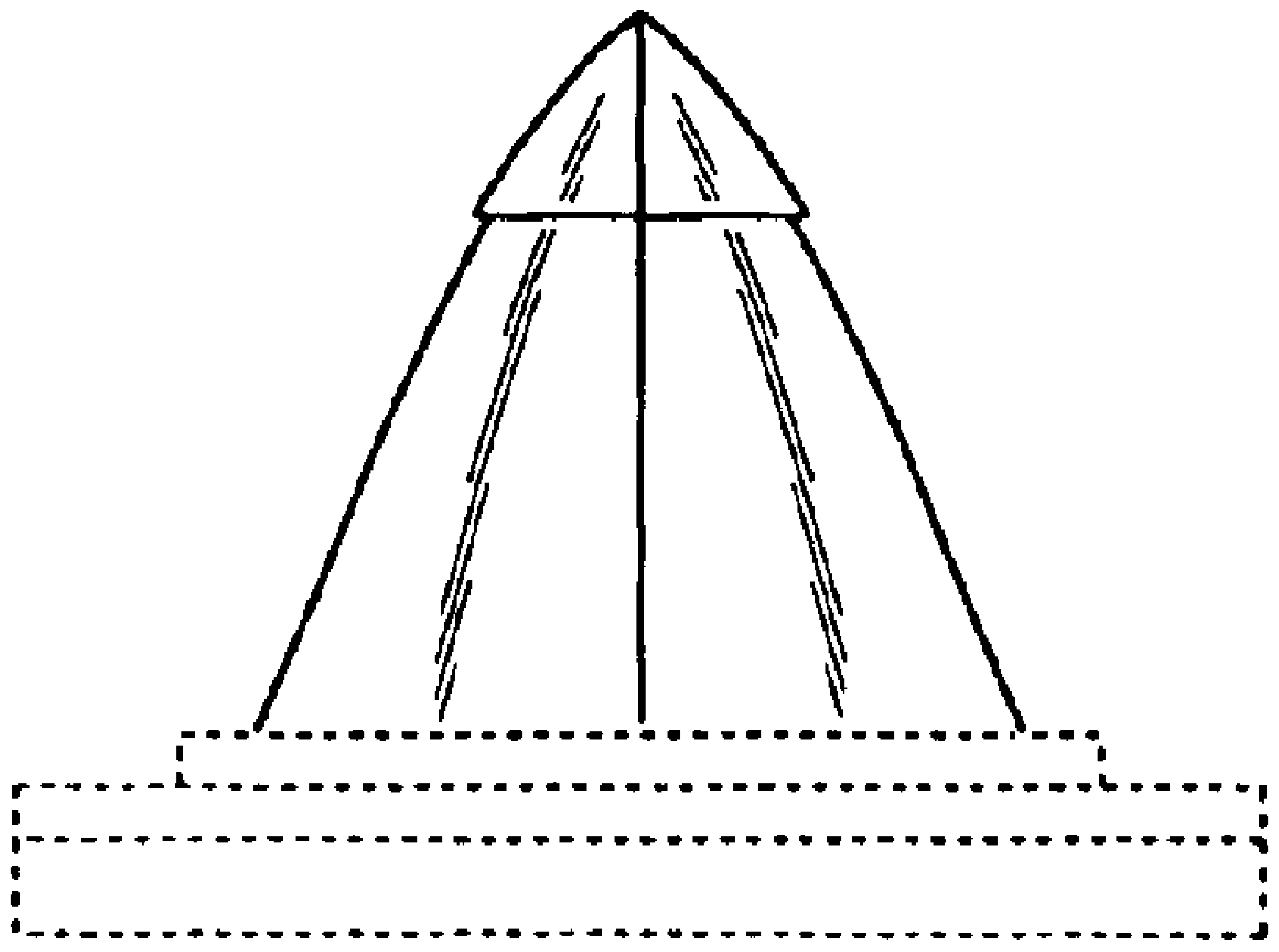


FIG. 5

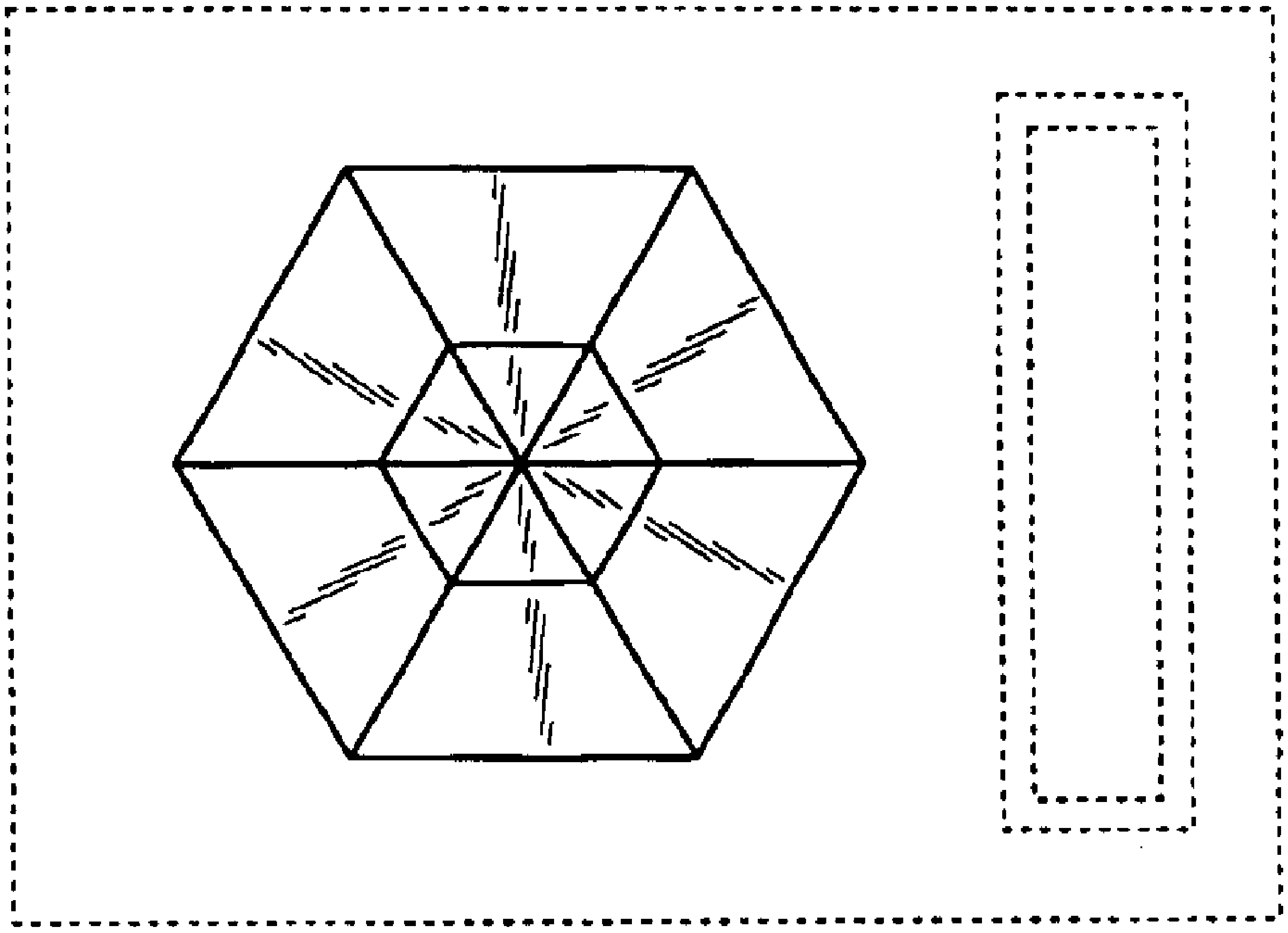


FIG. 6

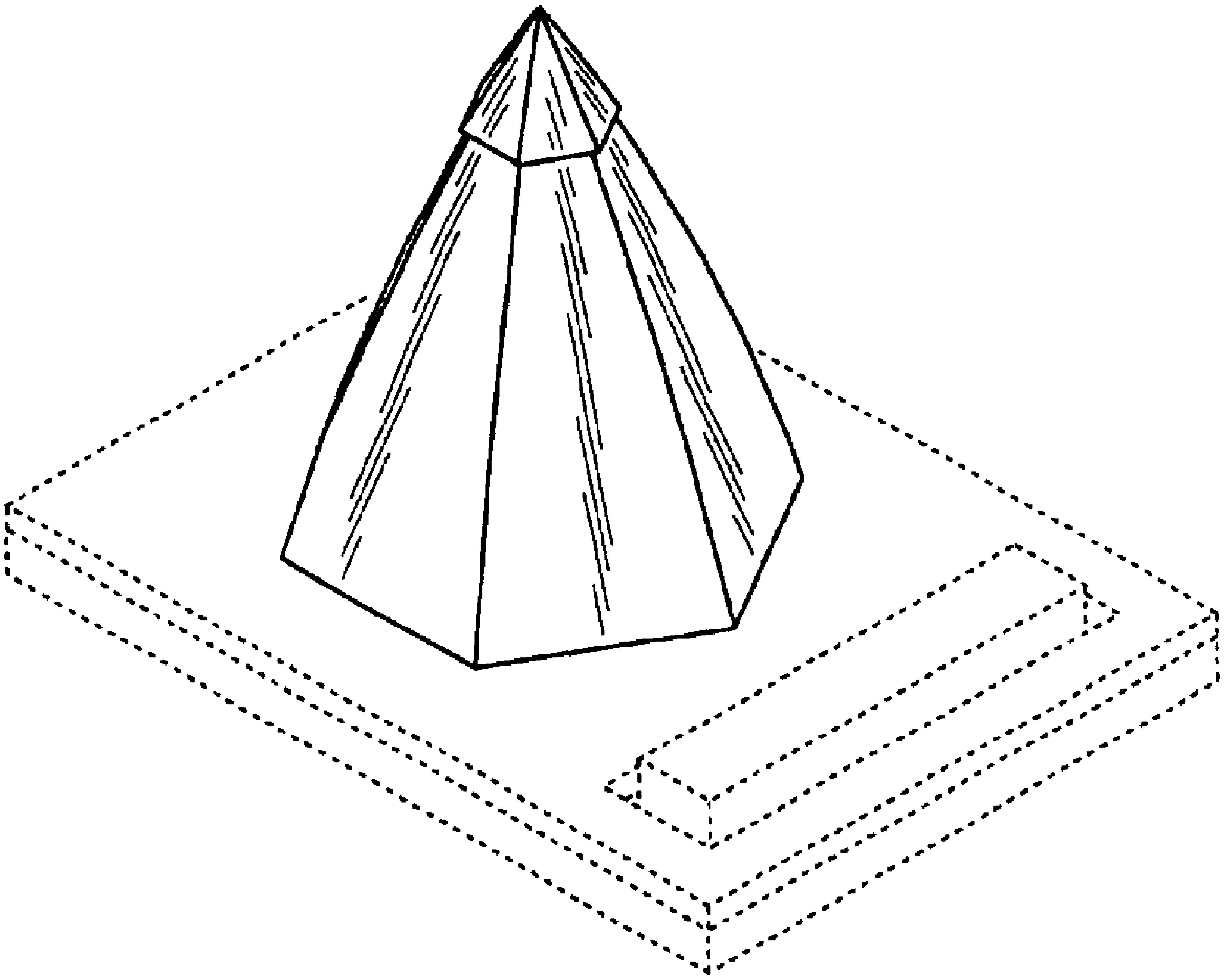


FIG. 7

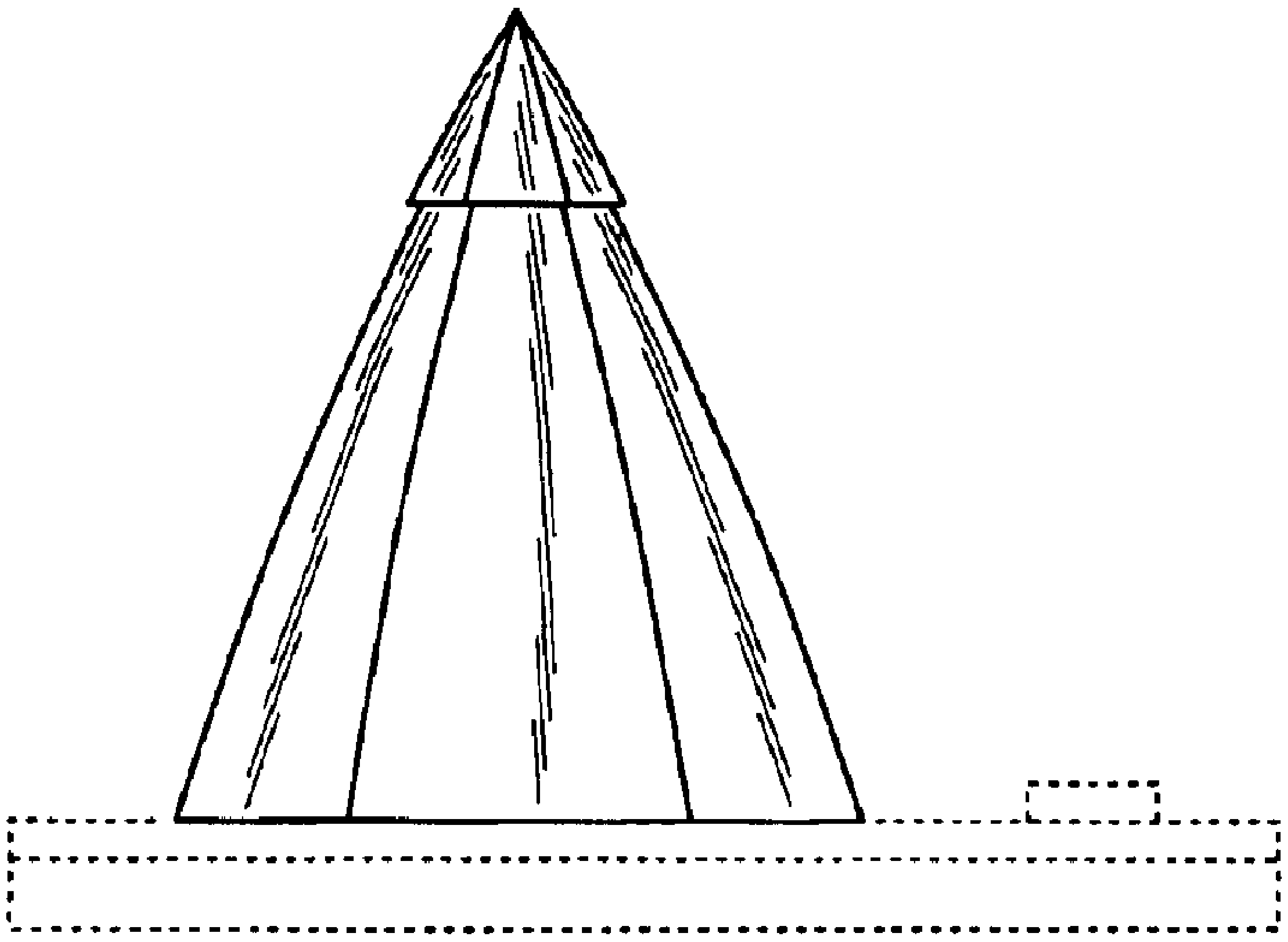


FIG. 8

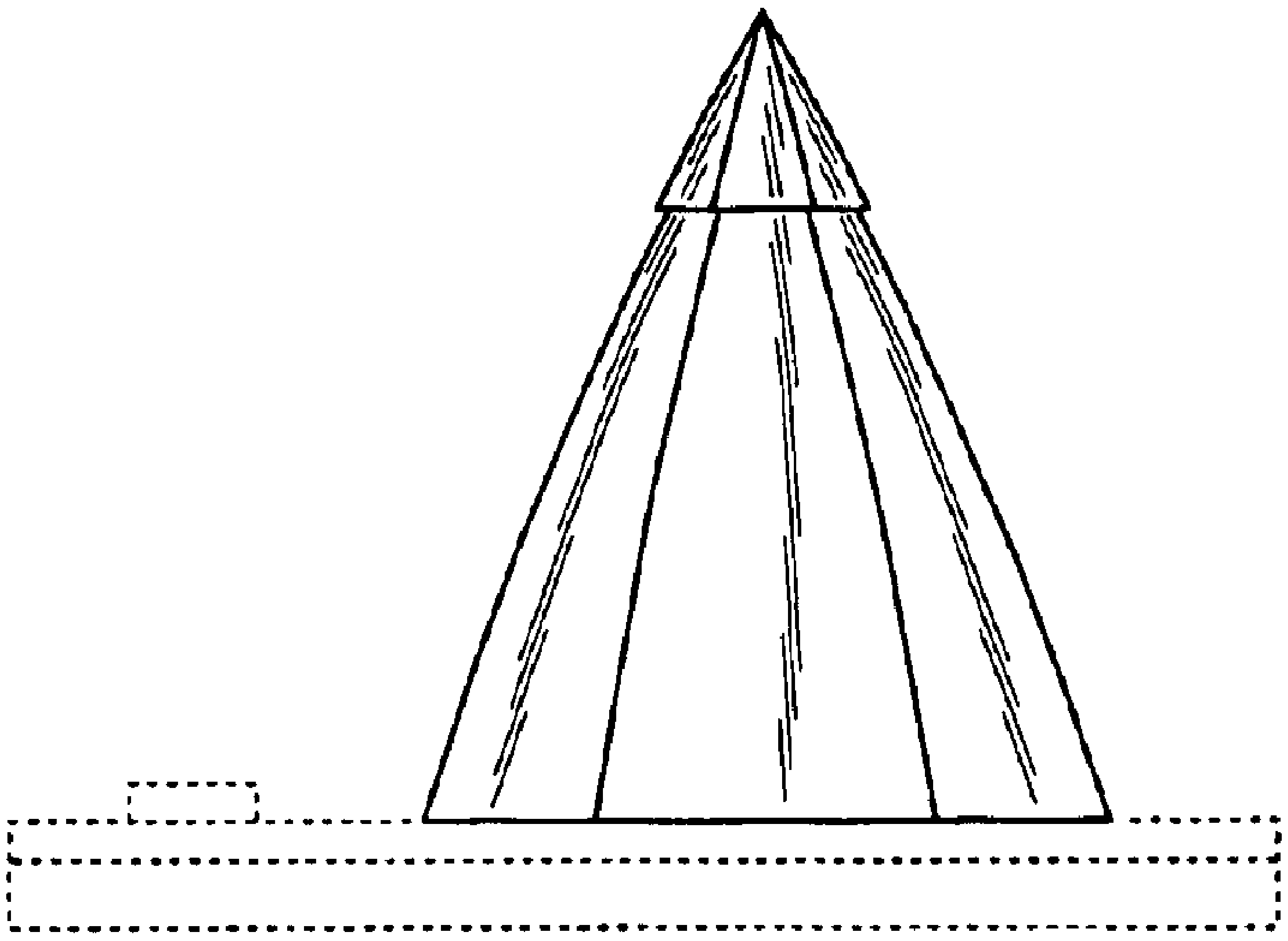


FIG. 9

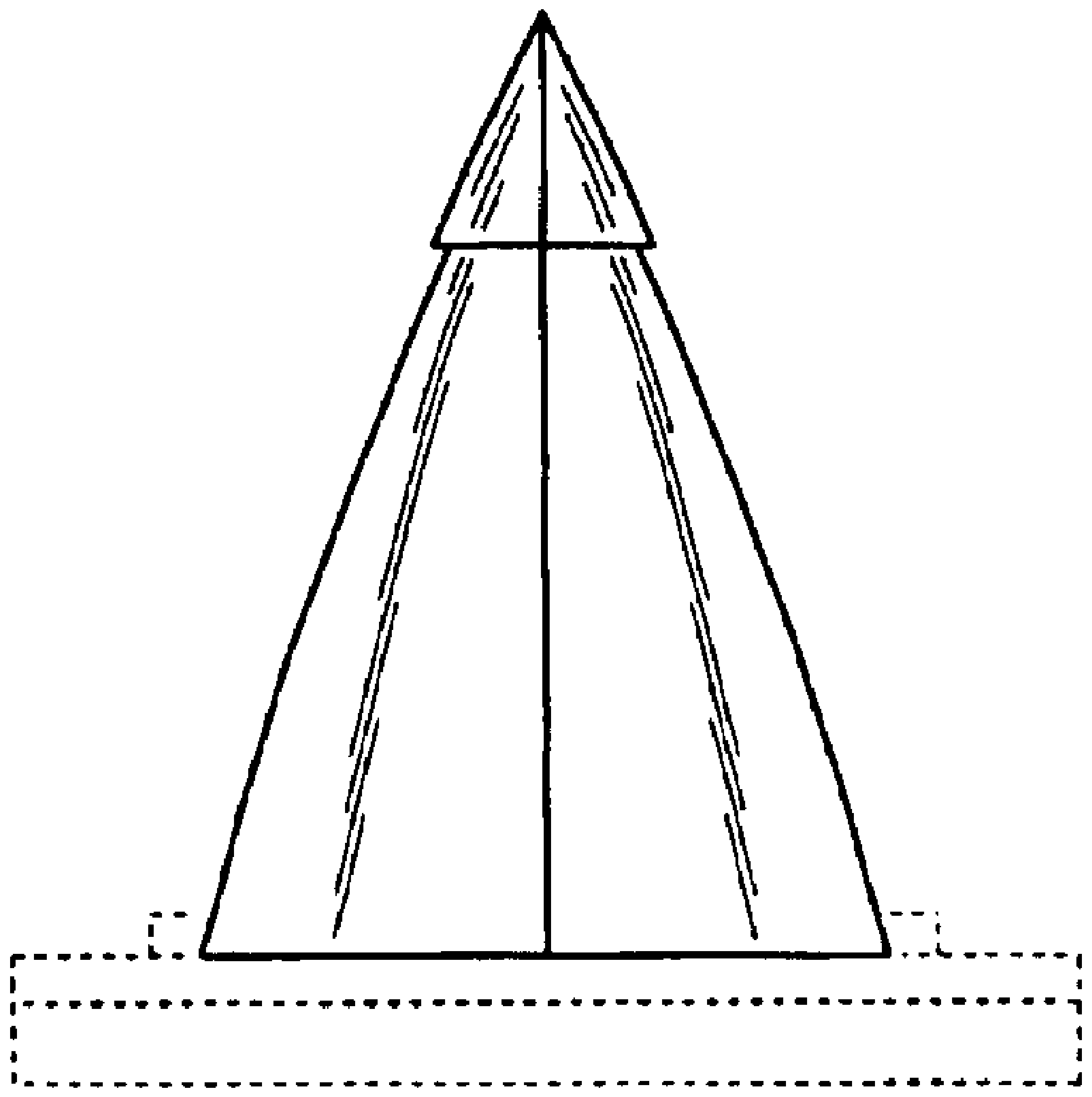


FIG. 10

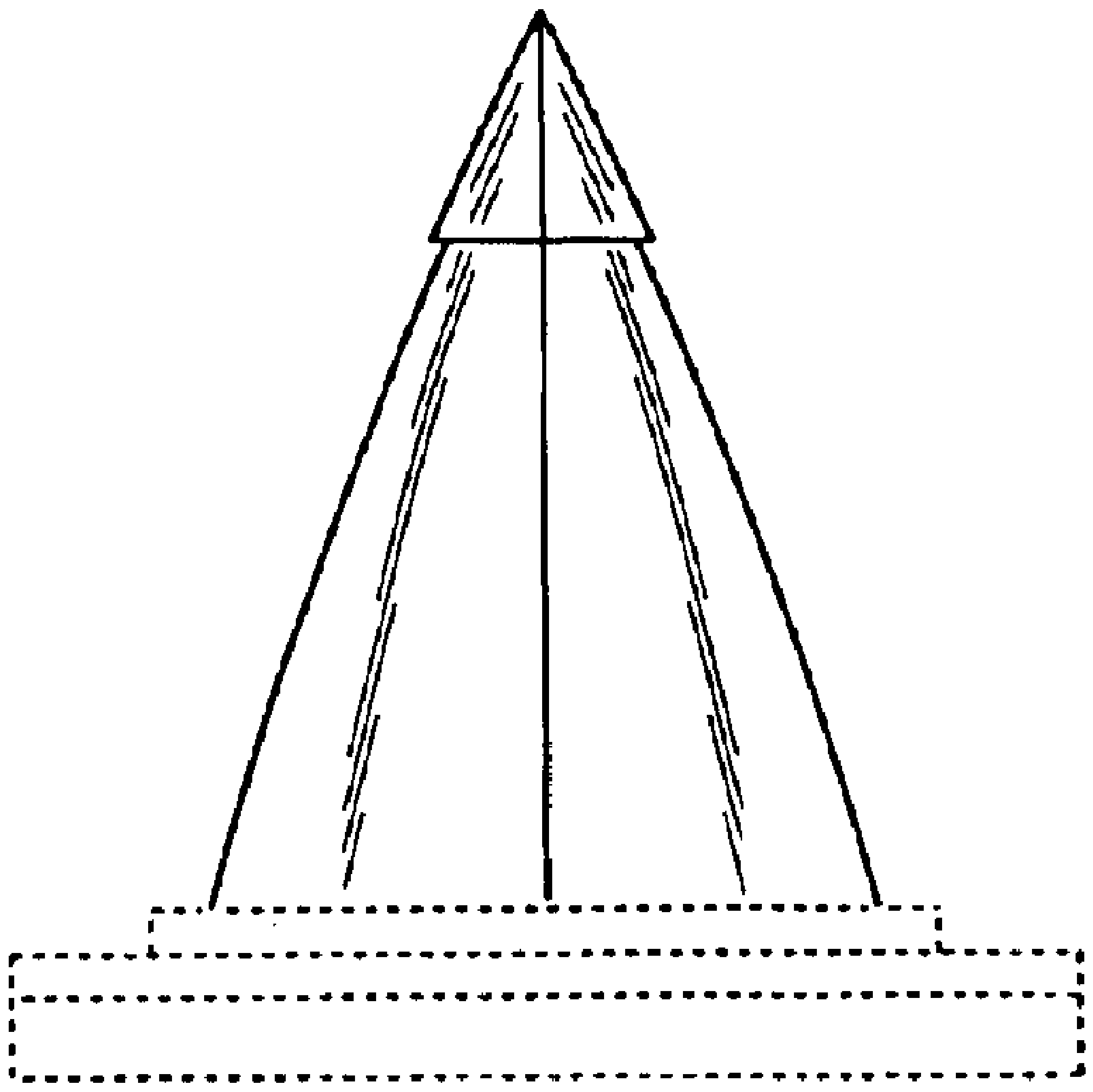


FIG. 11

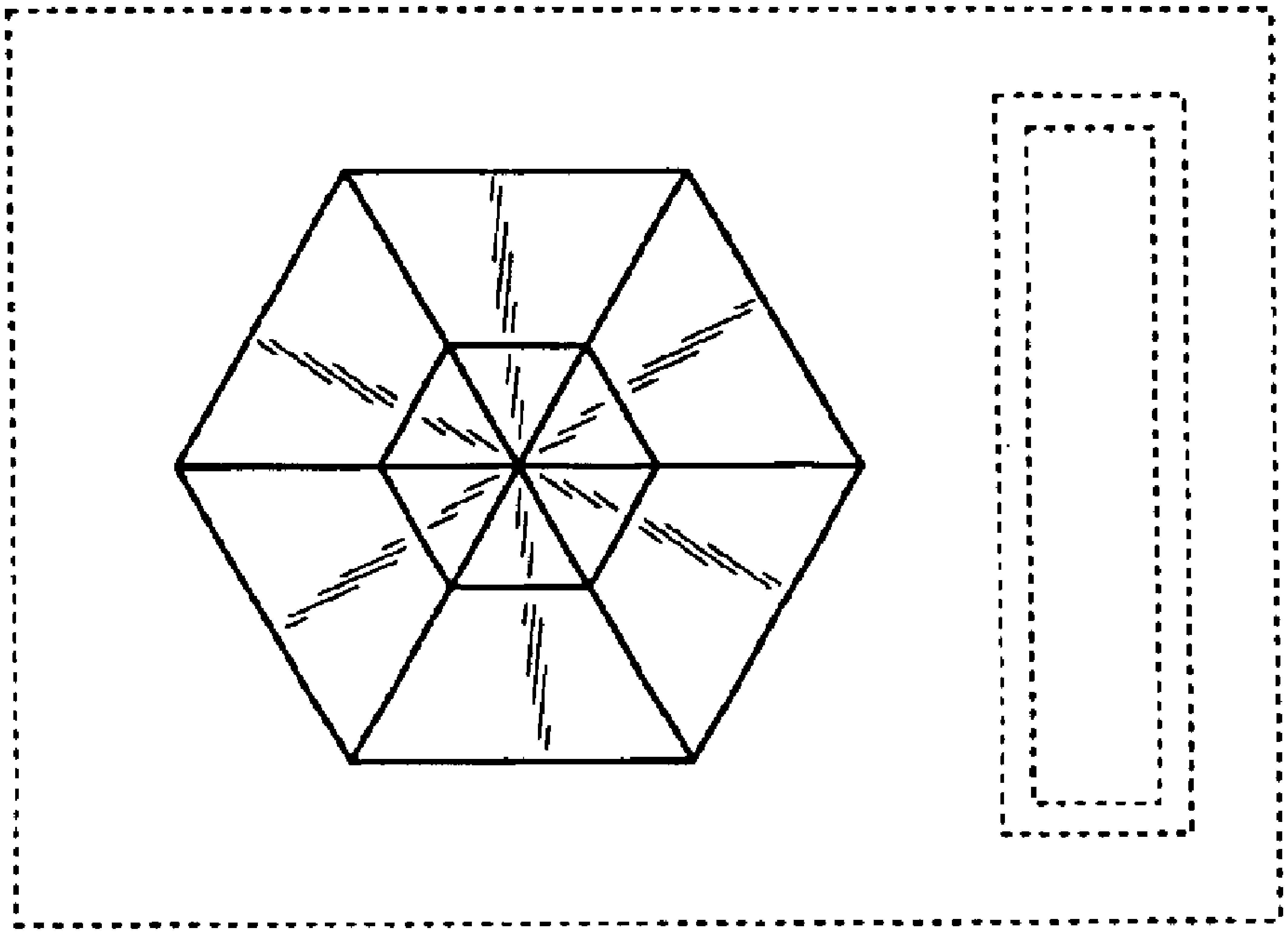


FIG. 12

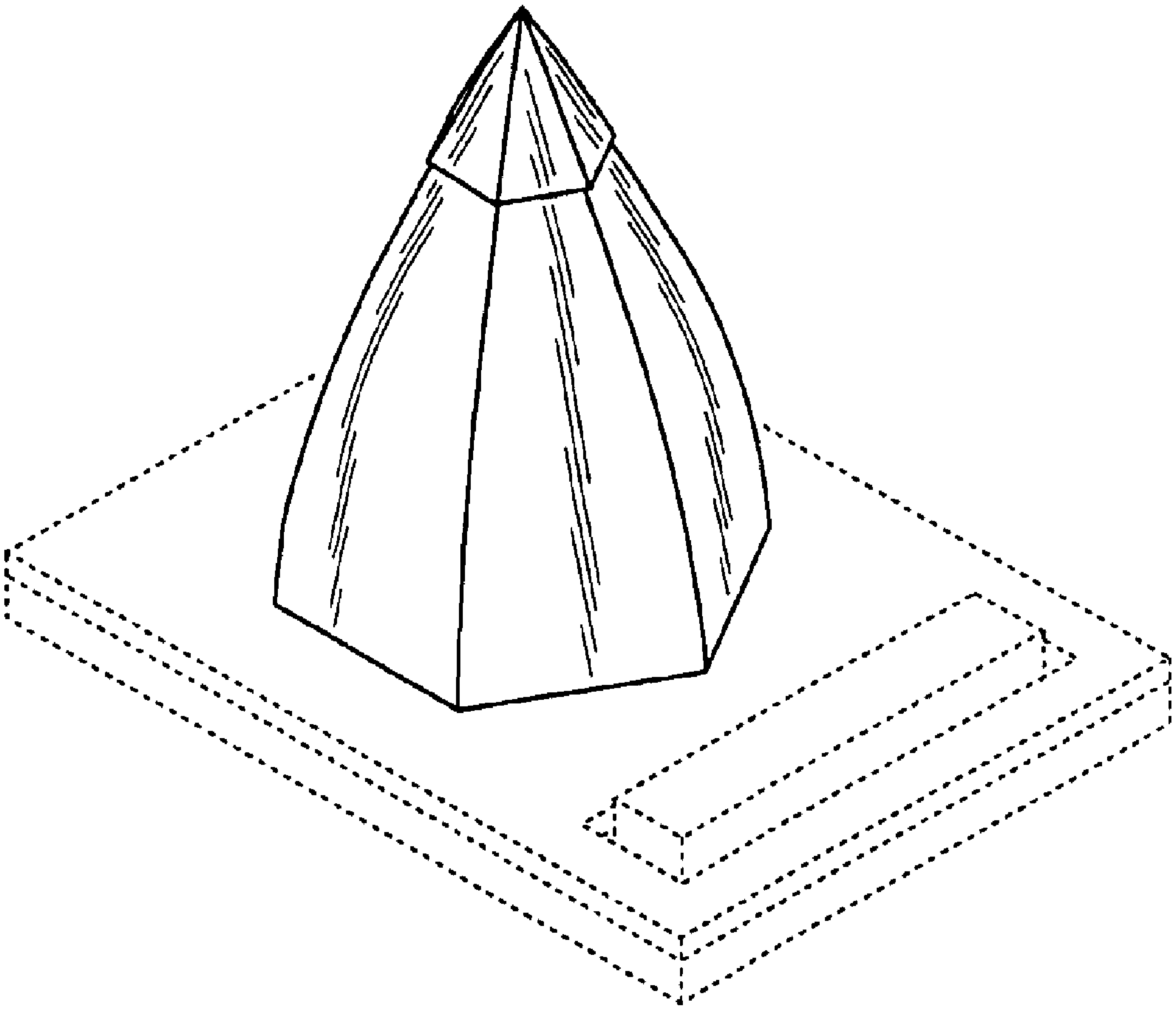


FIG. 13

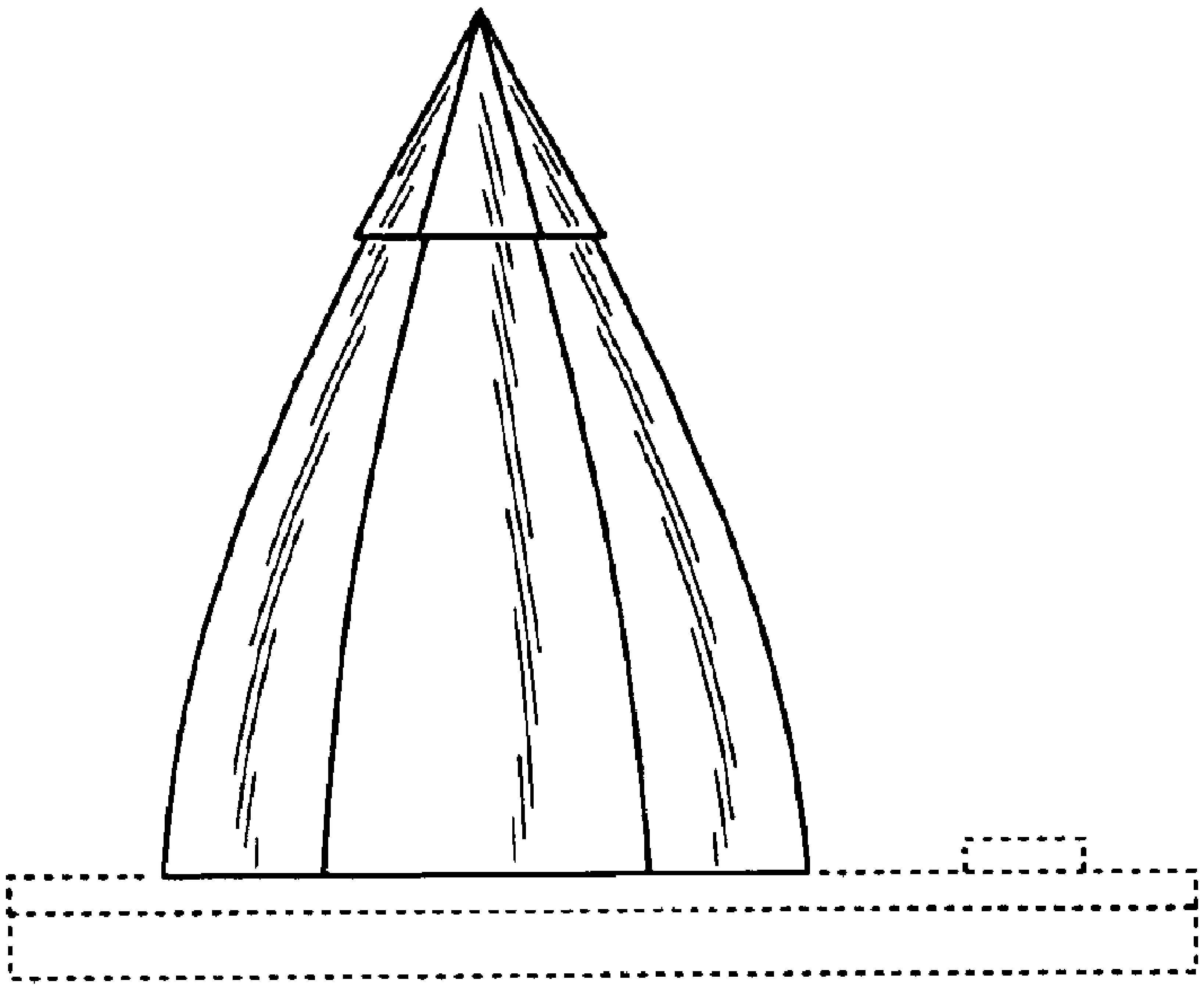


FIG. 14

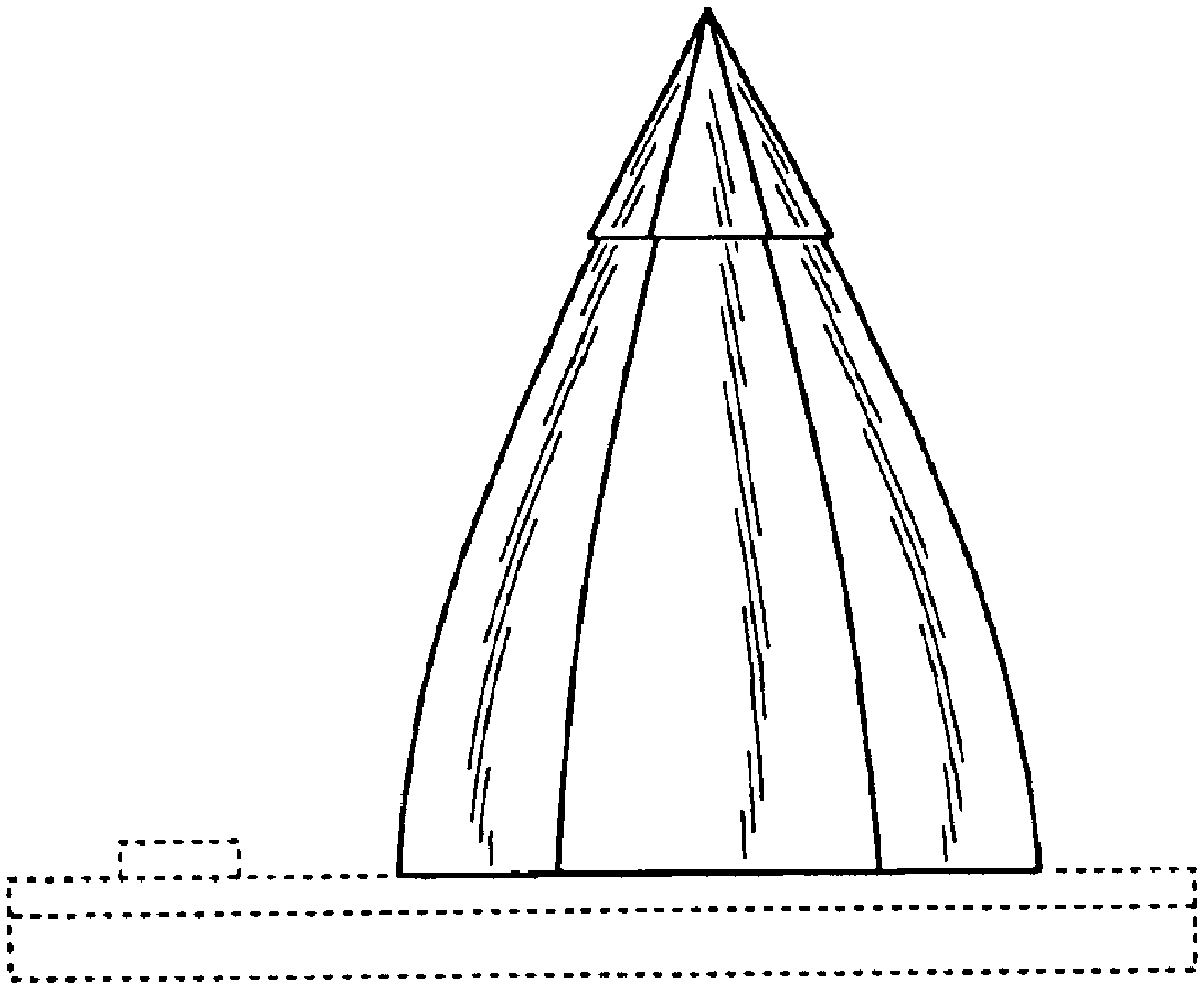


FIG. 15

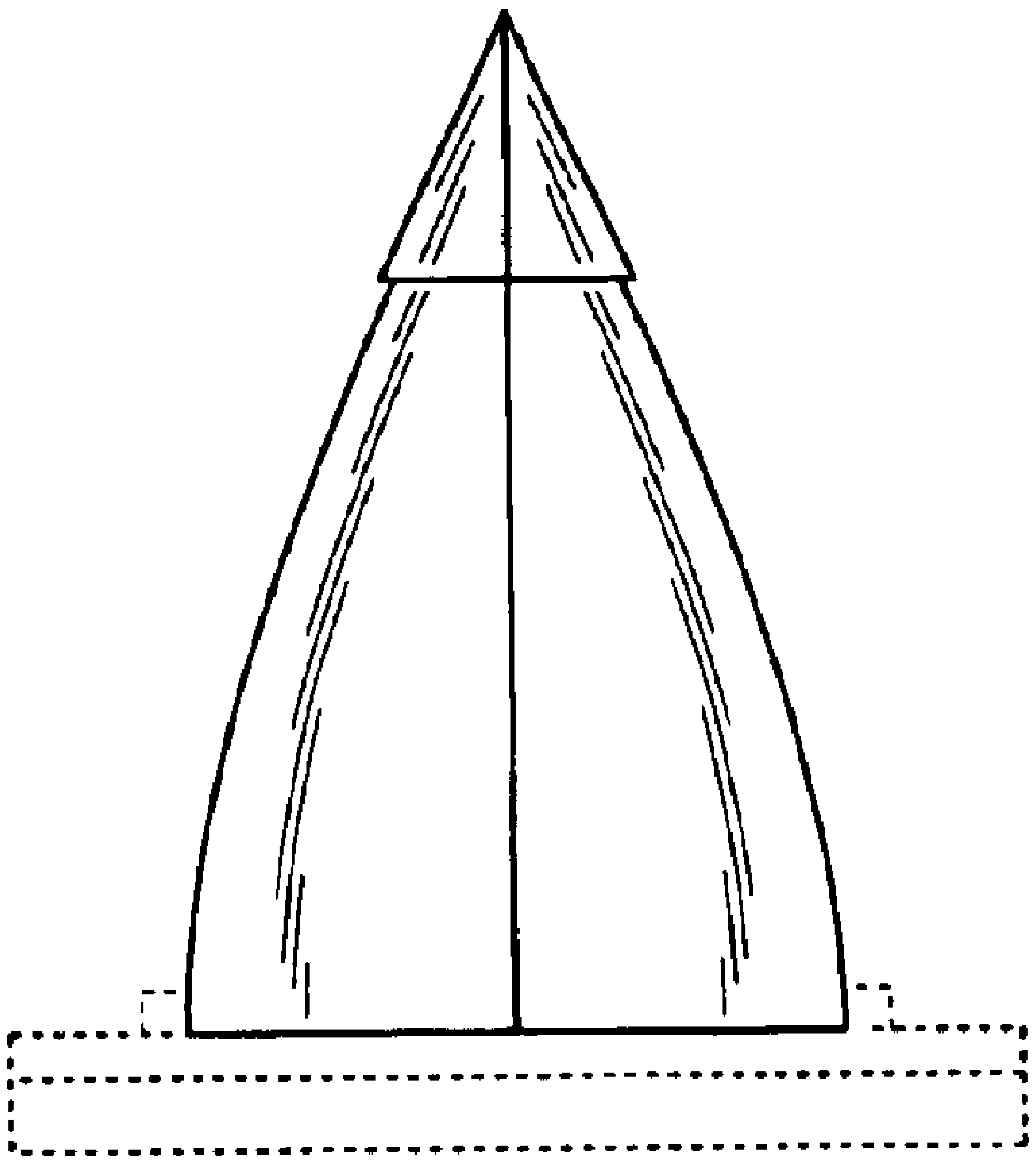


FIG. 16

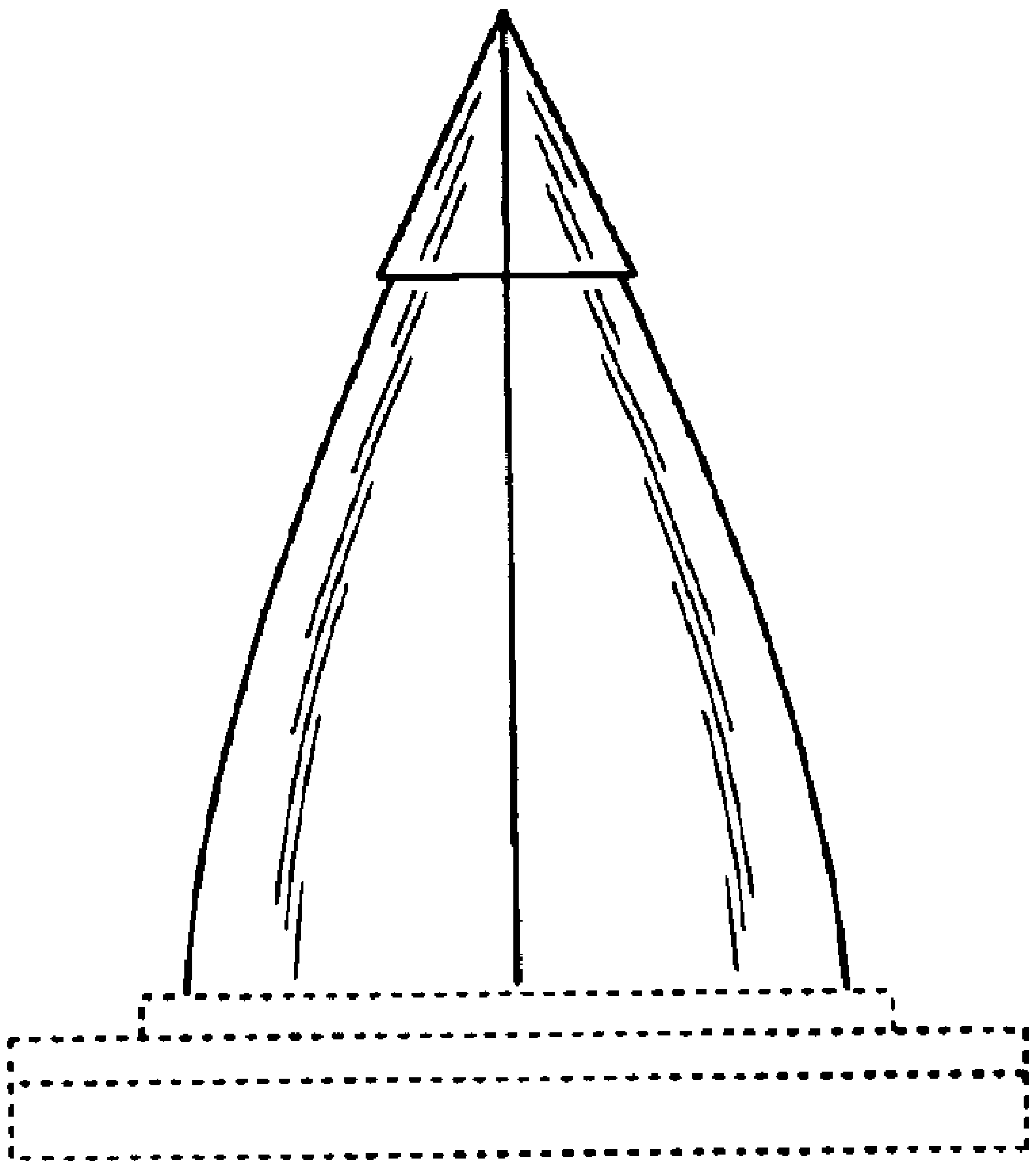


FIG. 17

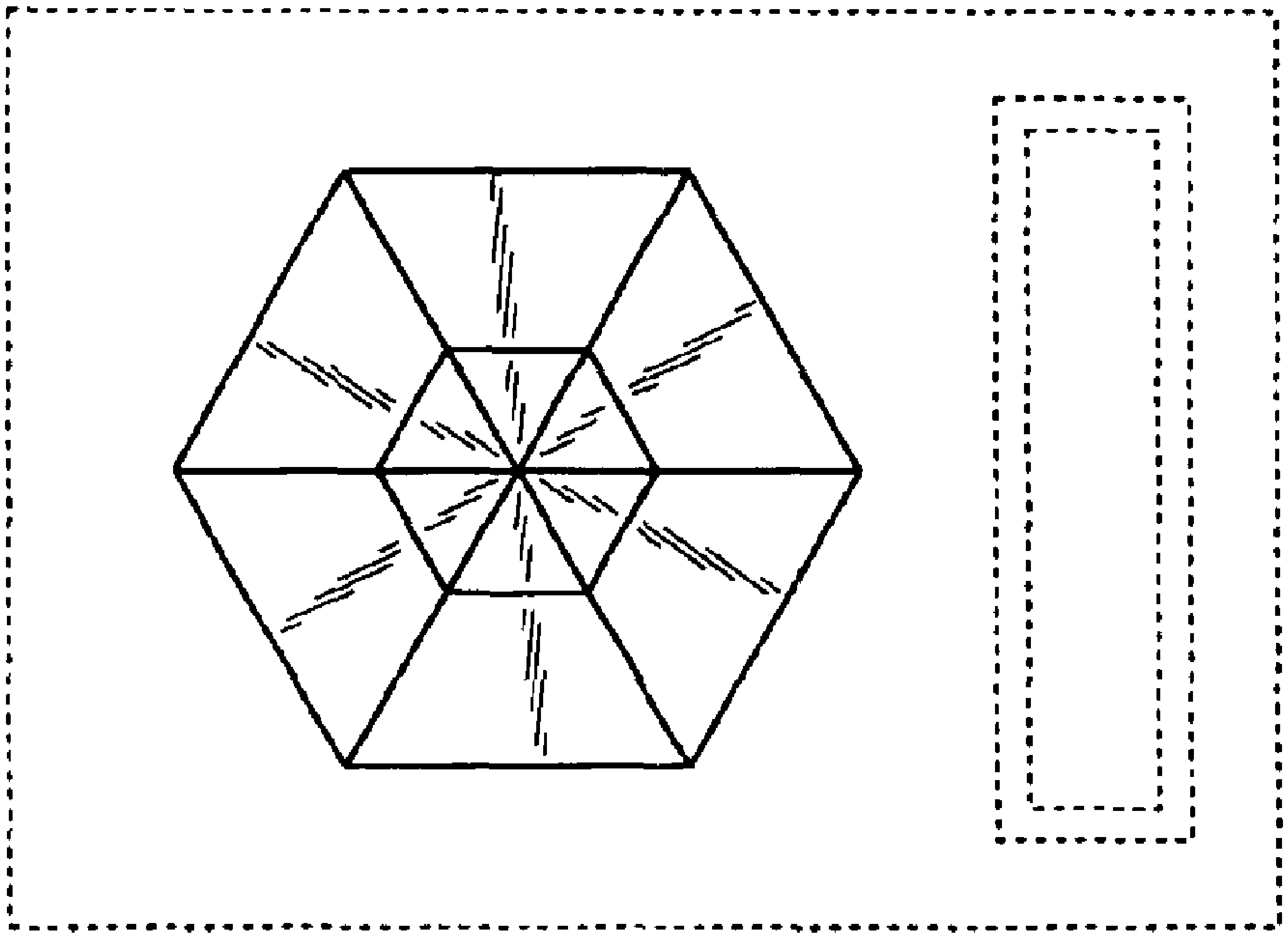
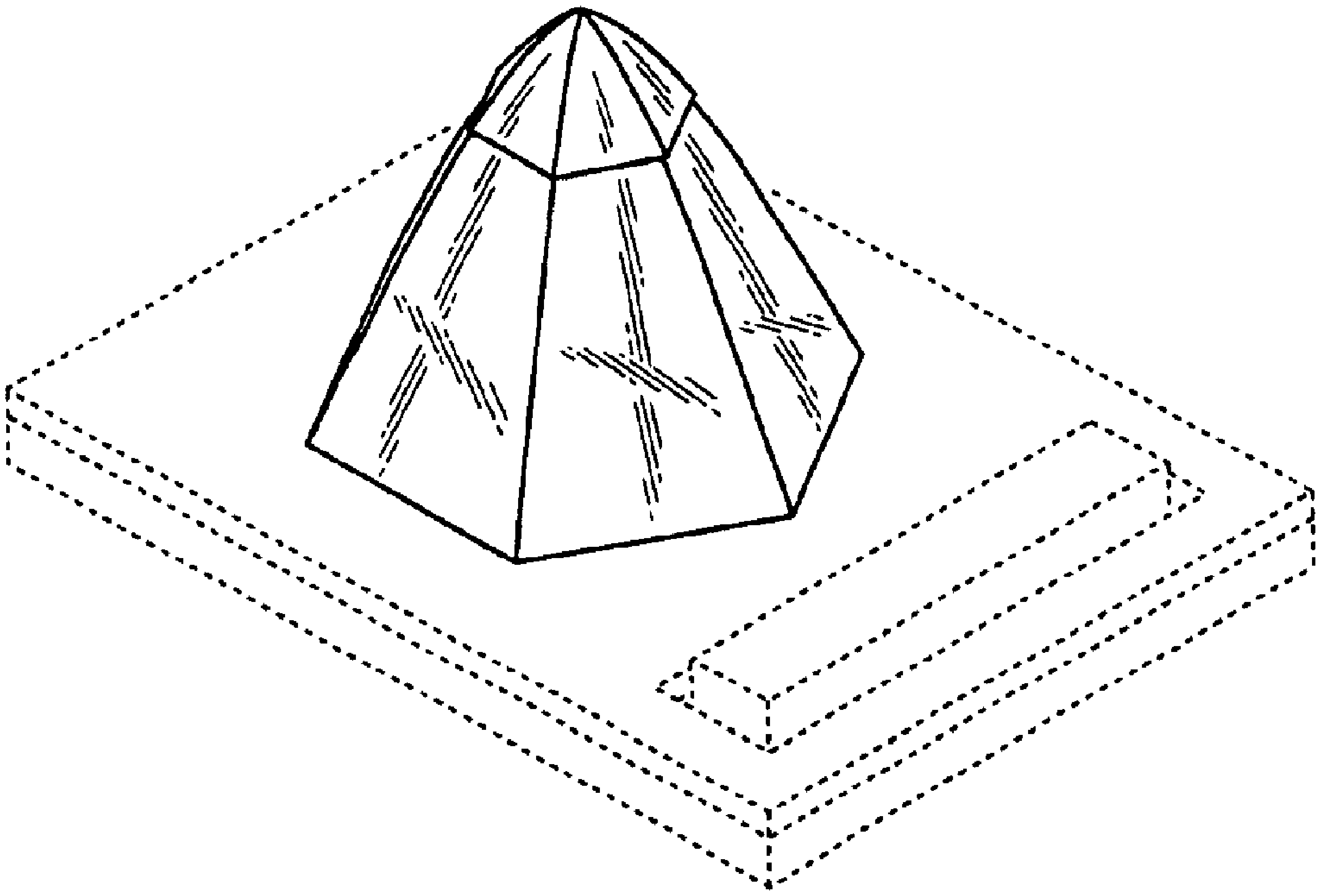


FIG. 18



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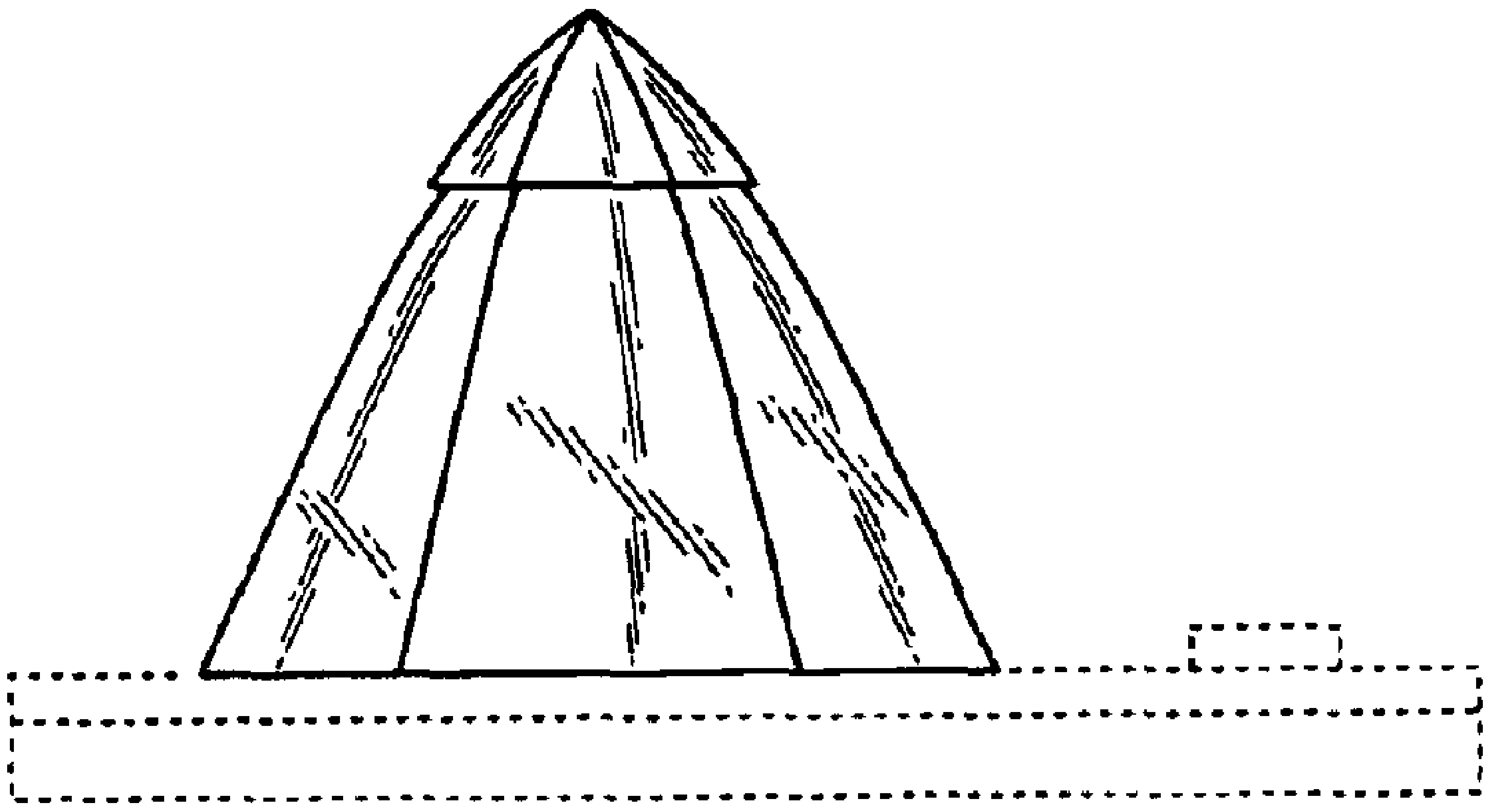

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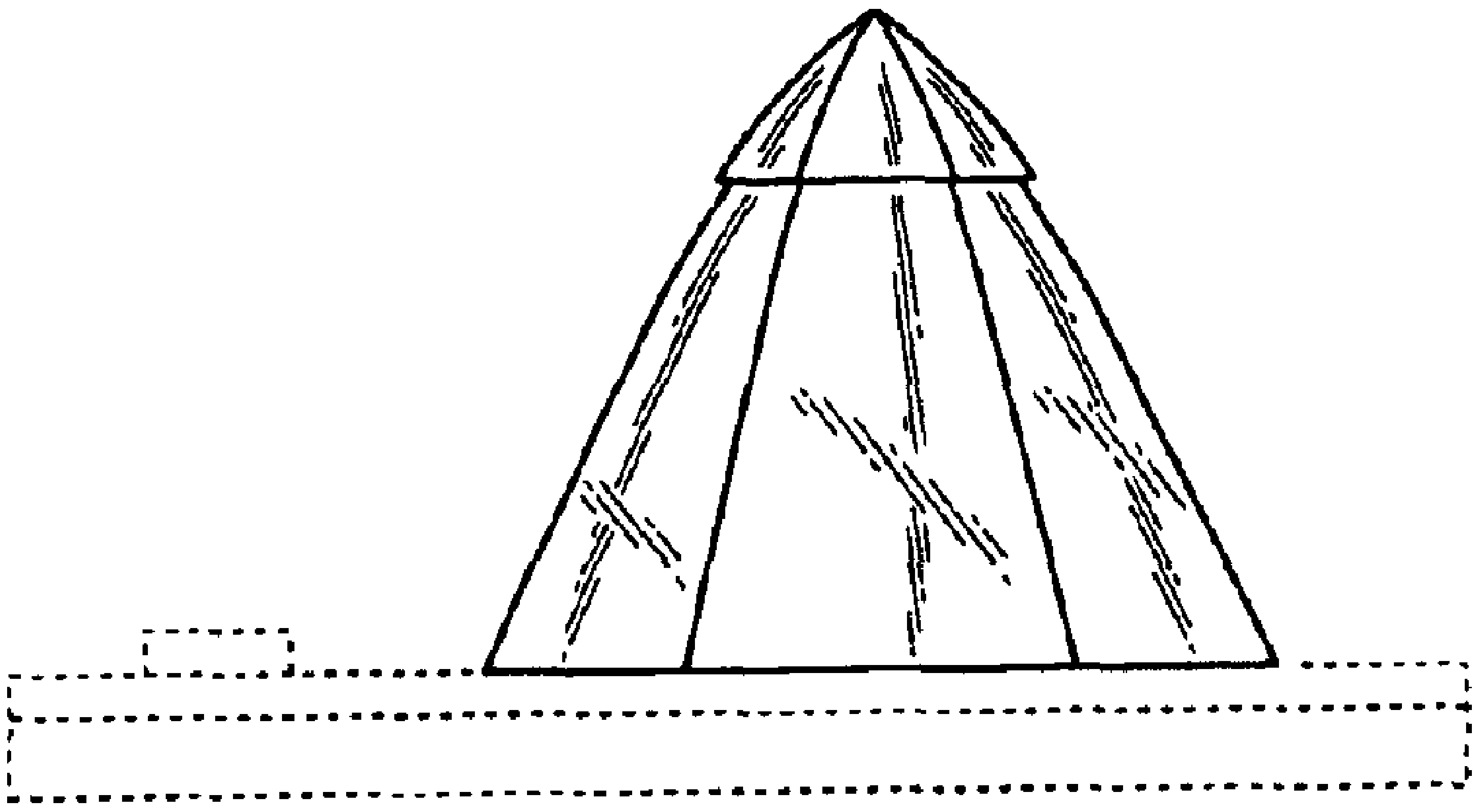


FIG. 21

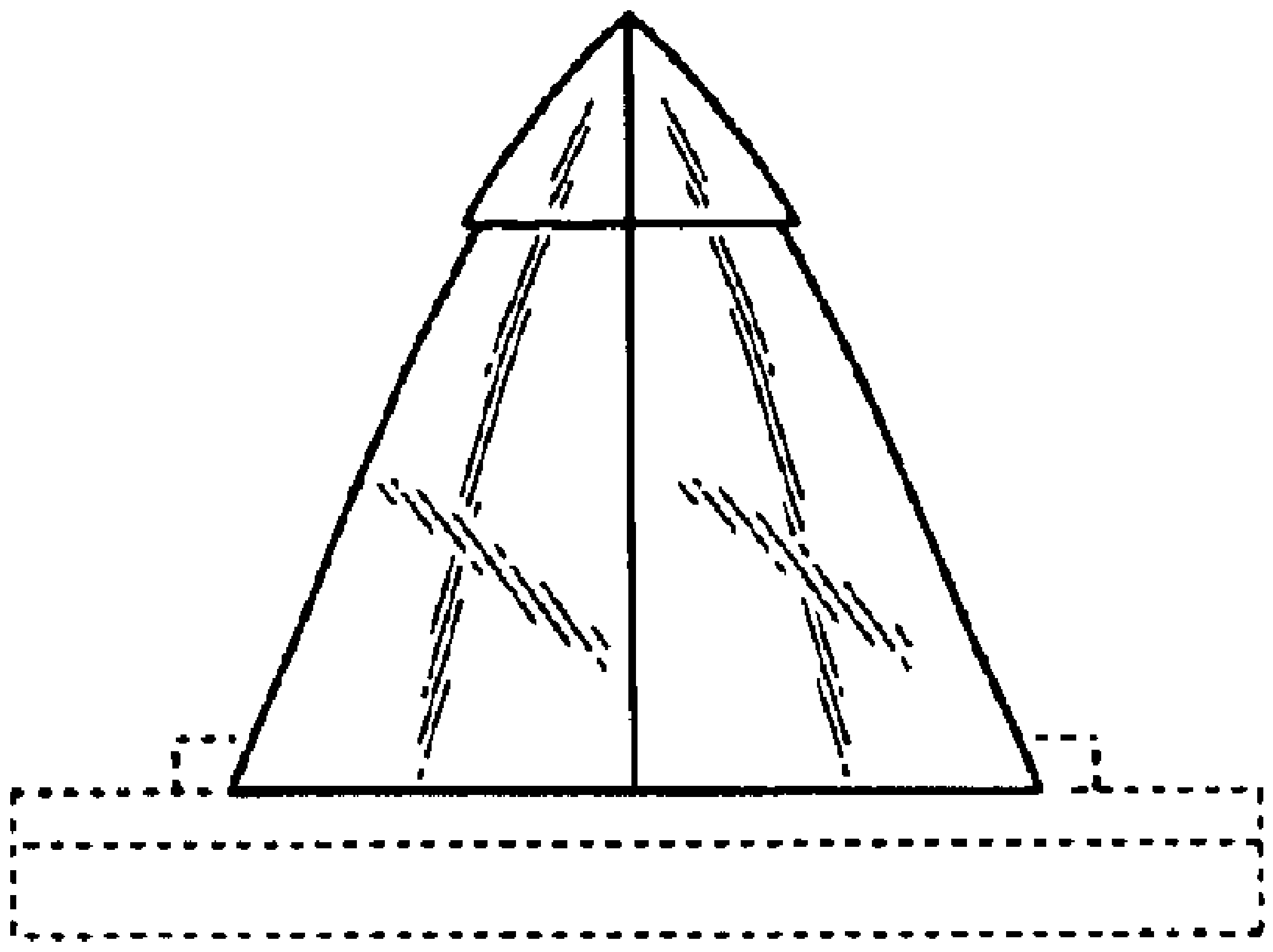
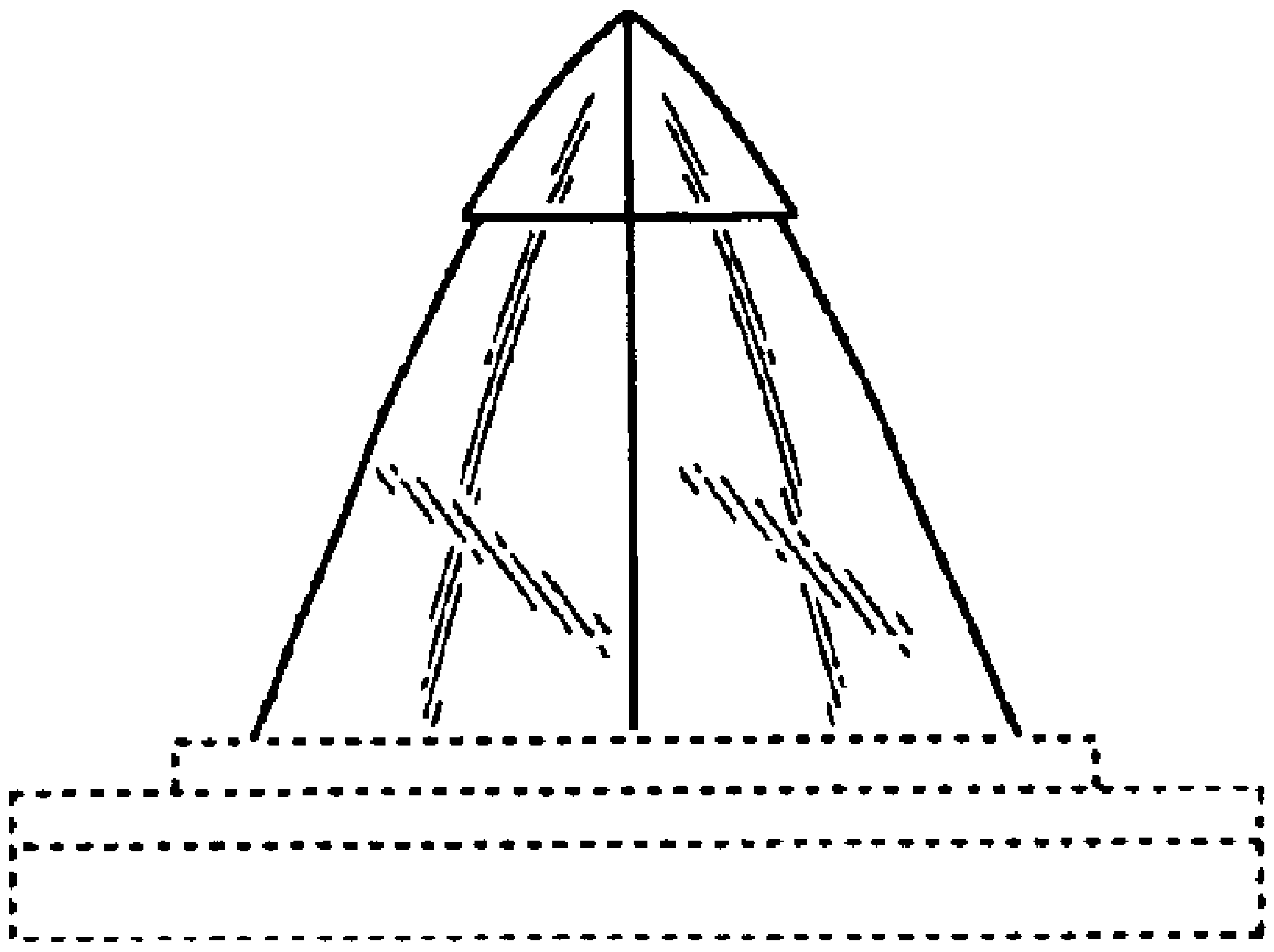


FIG. 22



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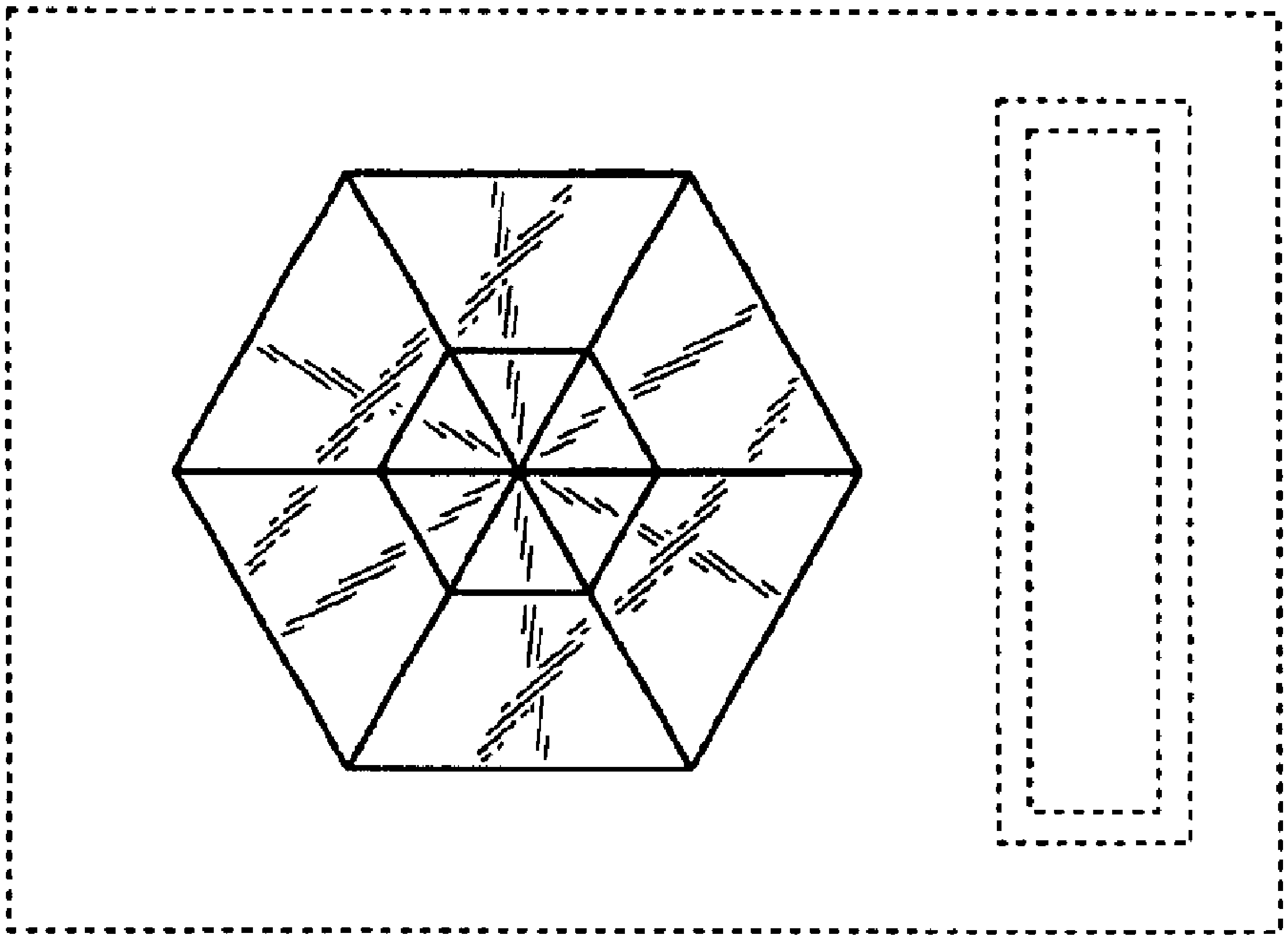


FIG. 24

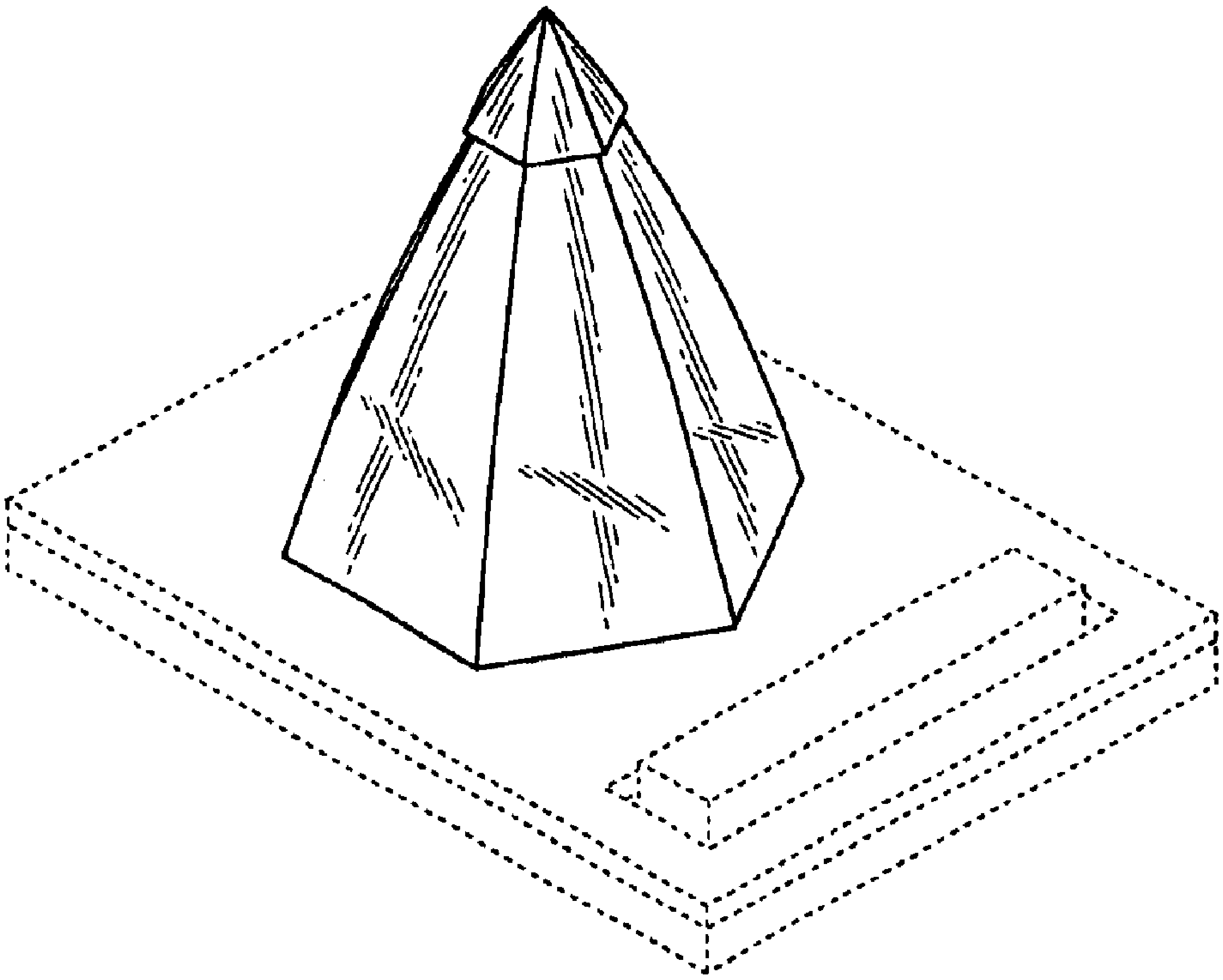


FIG. 25

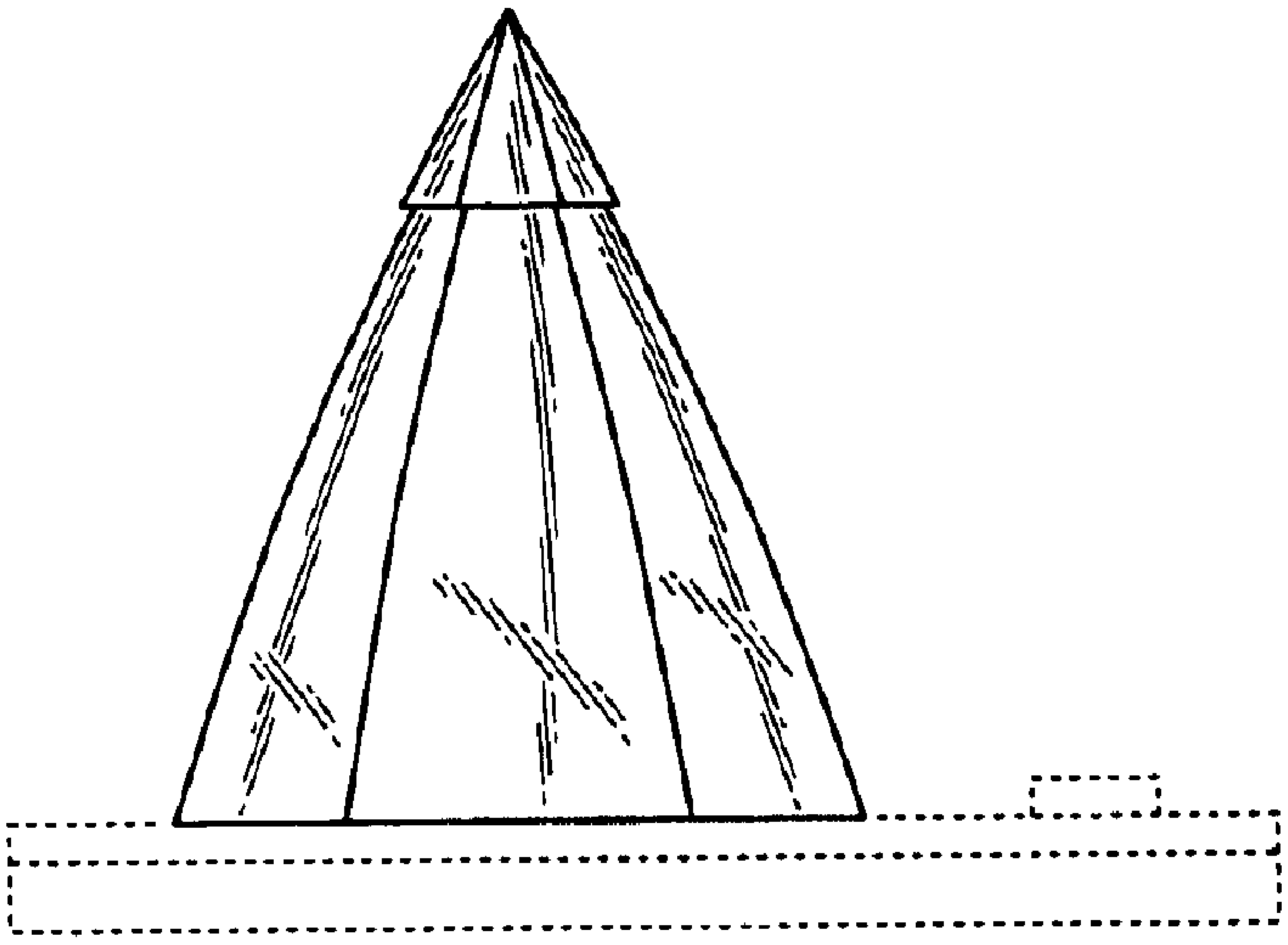


FIG. 26

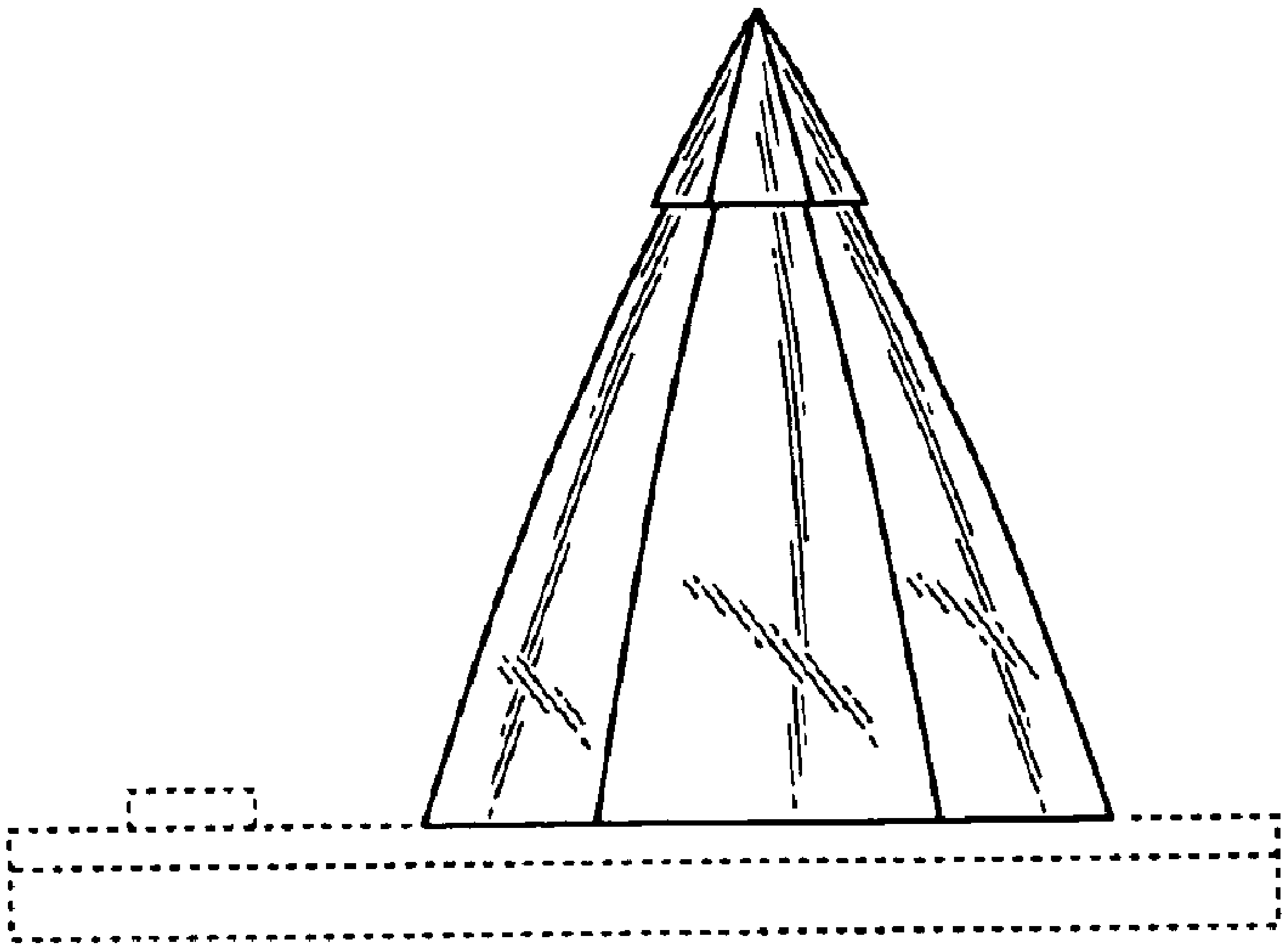


FIG. 27

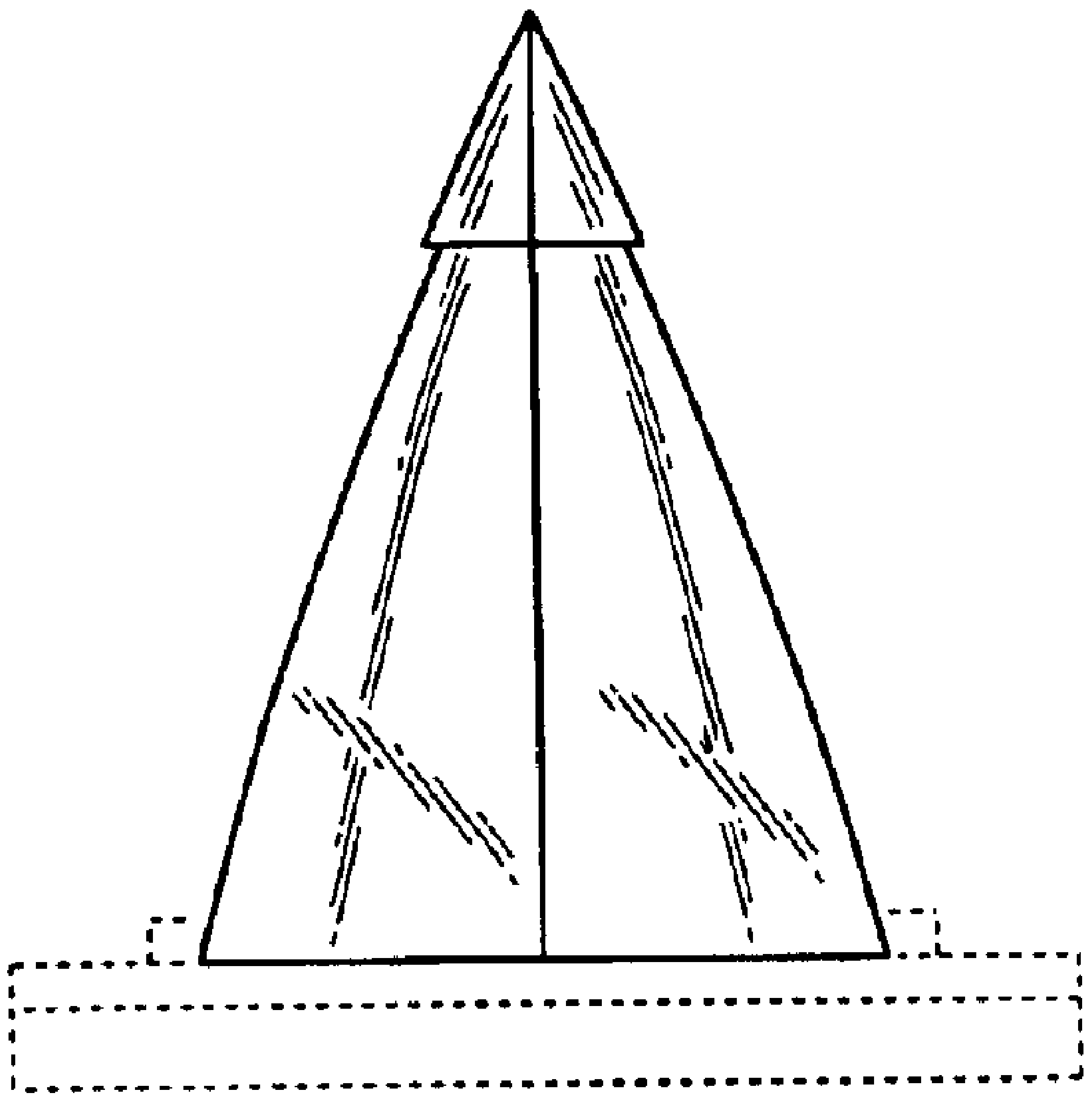


FIG. 28

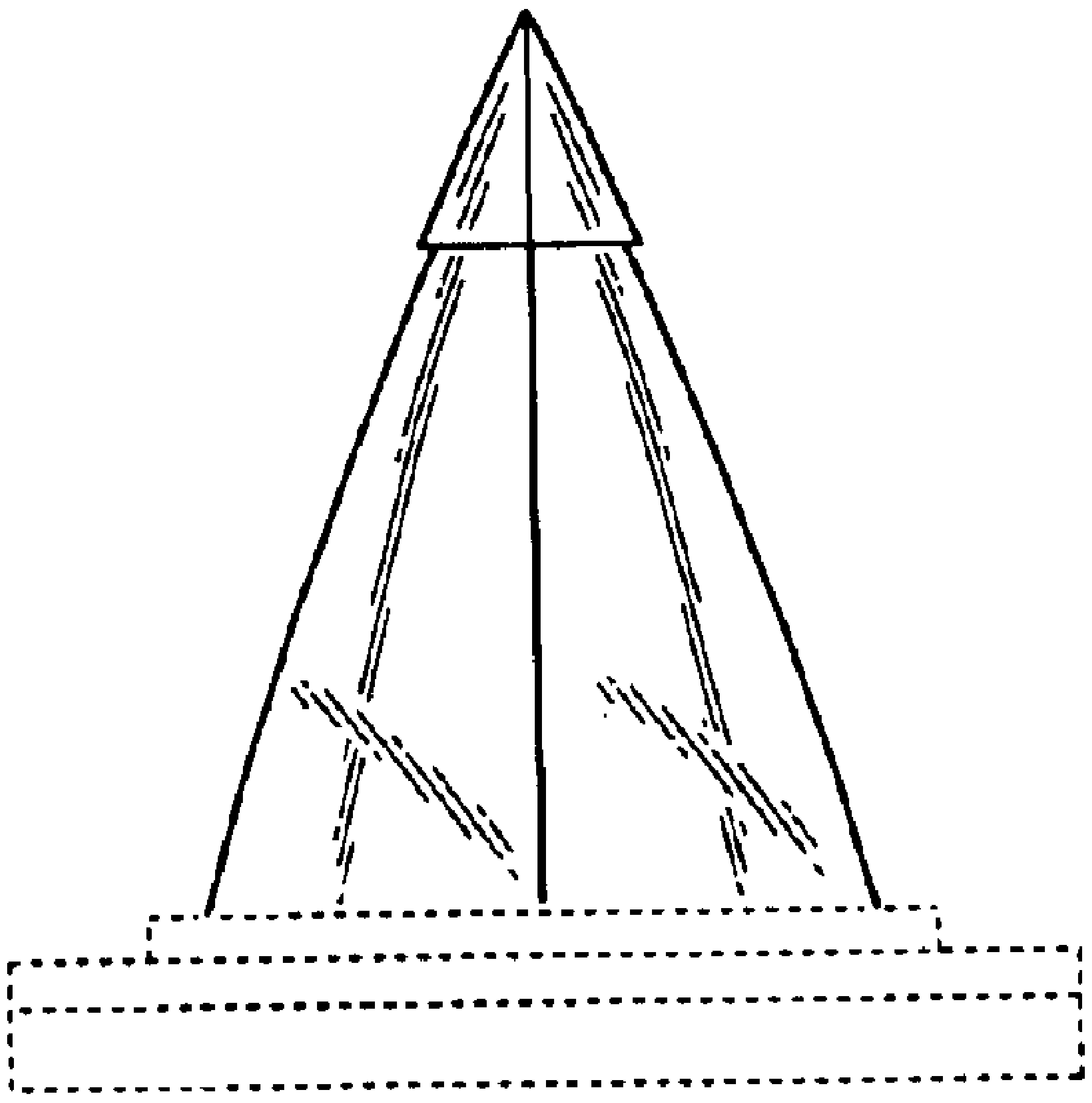
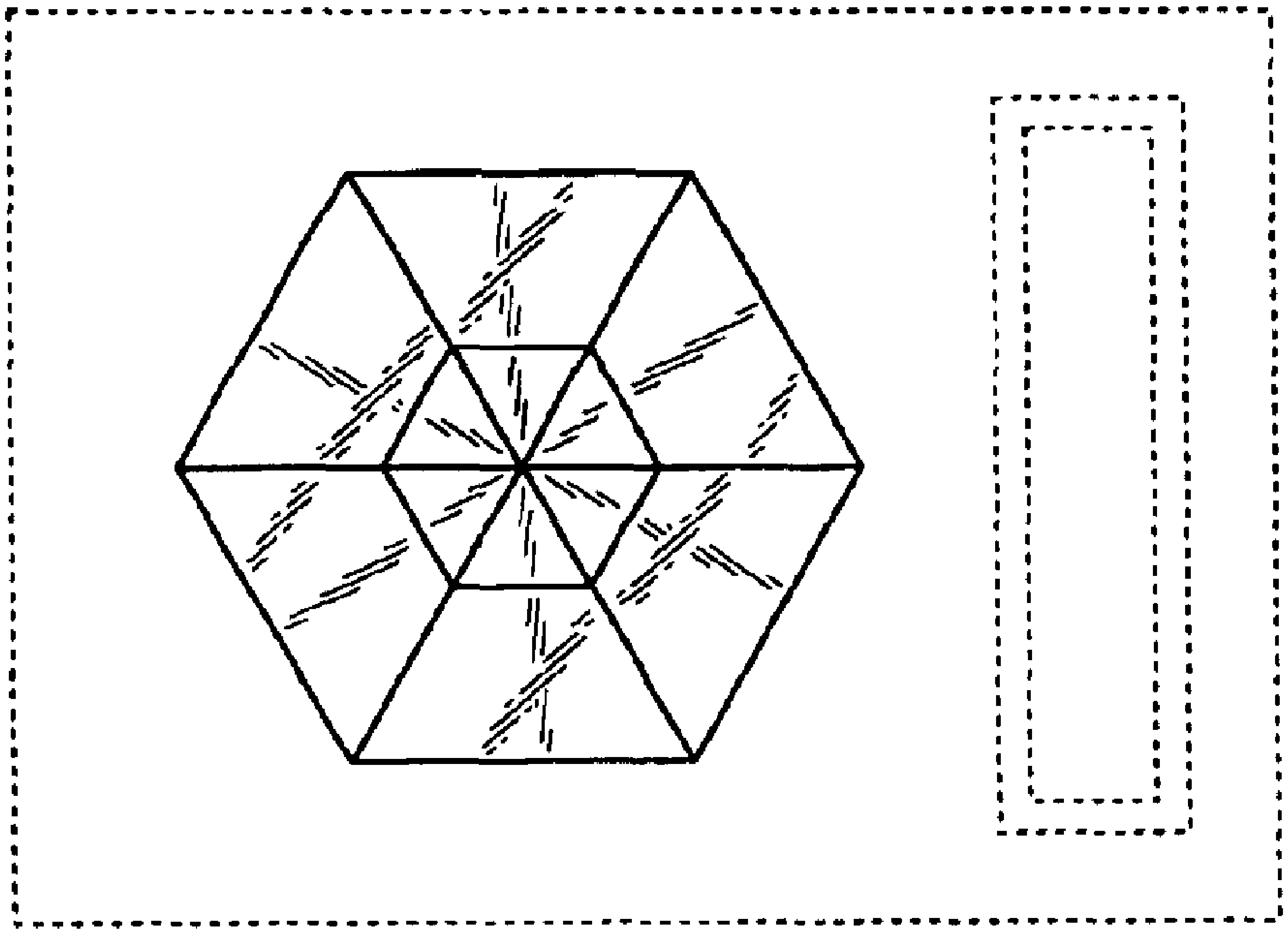


FIG. 29



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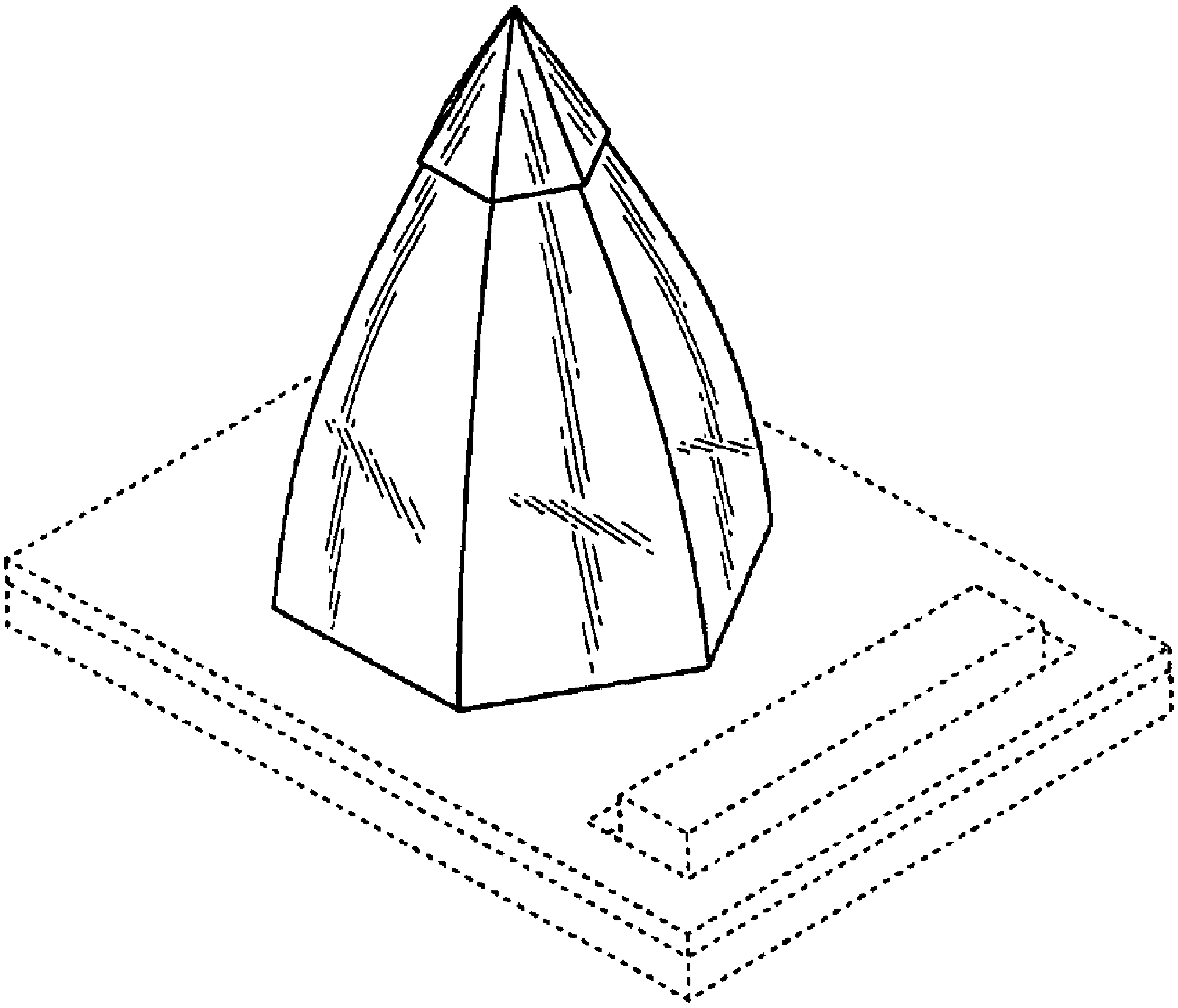

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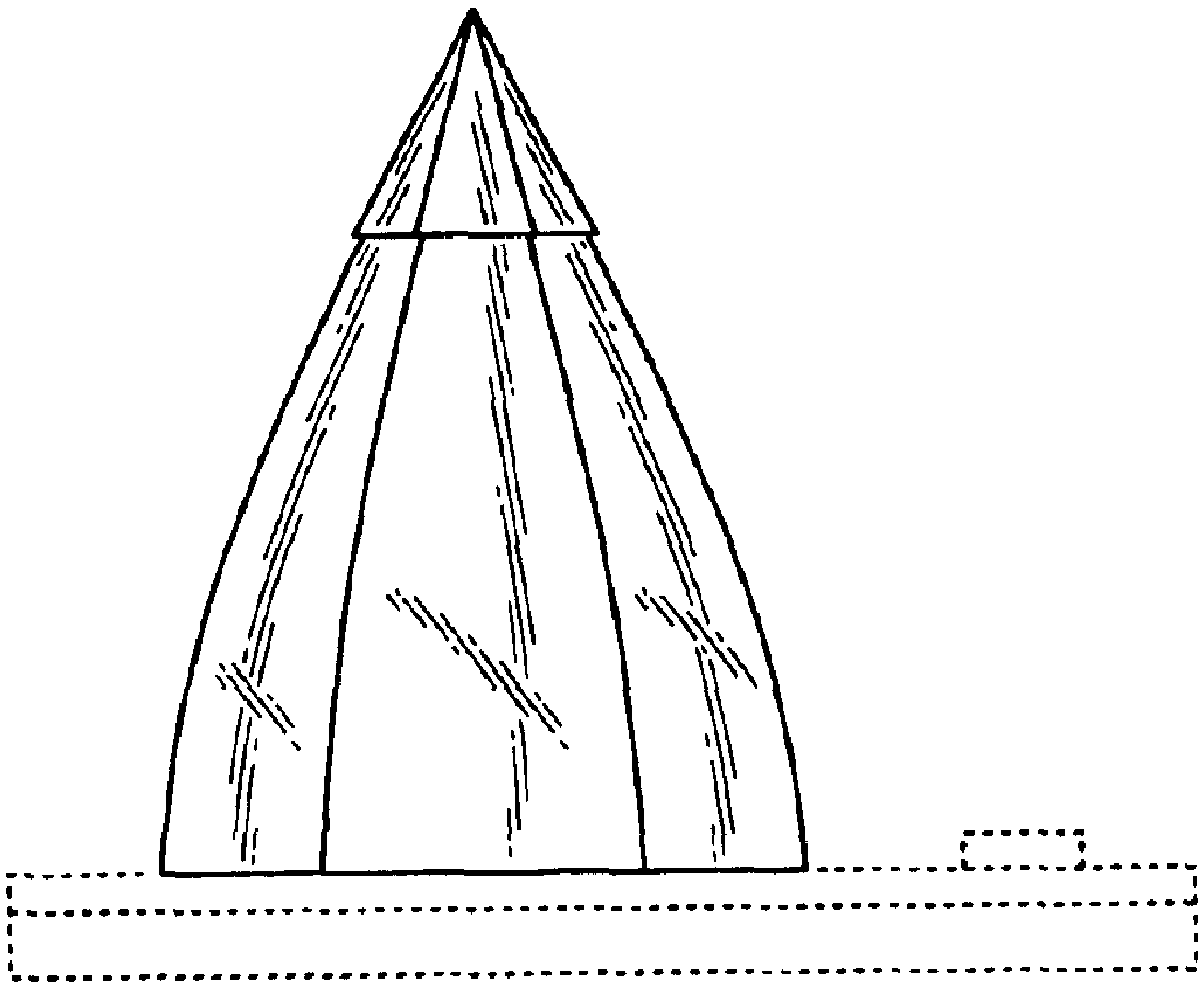

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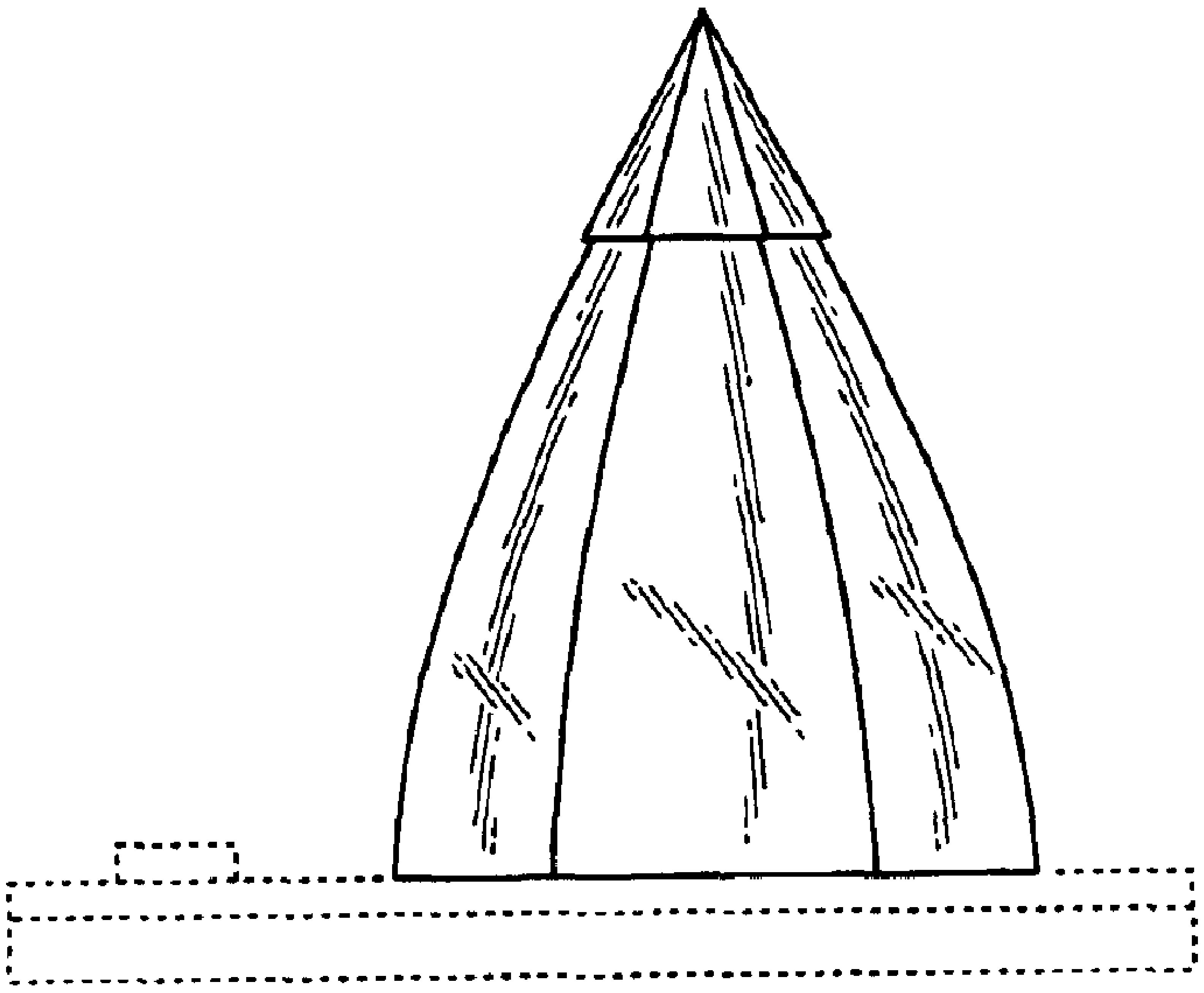

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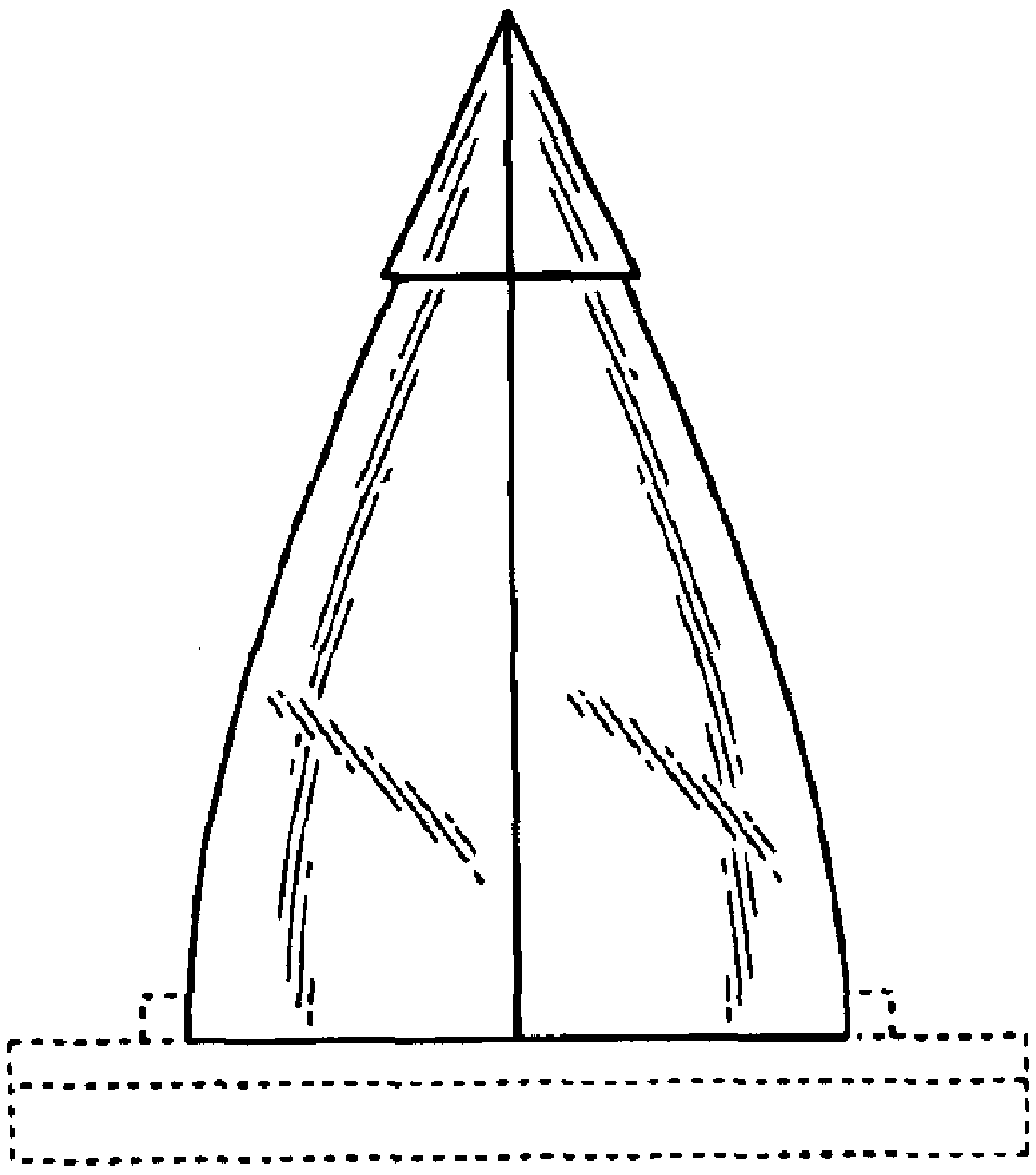

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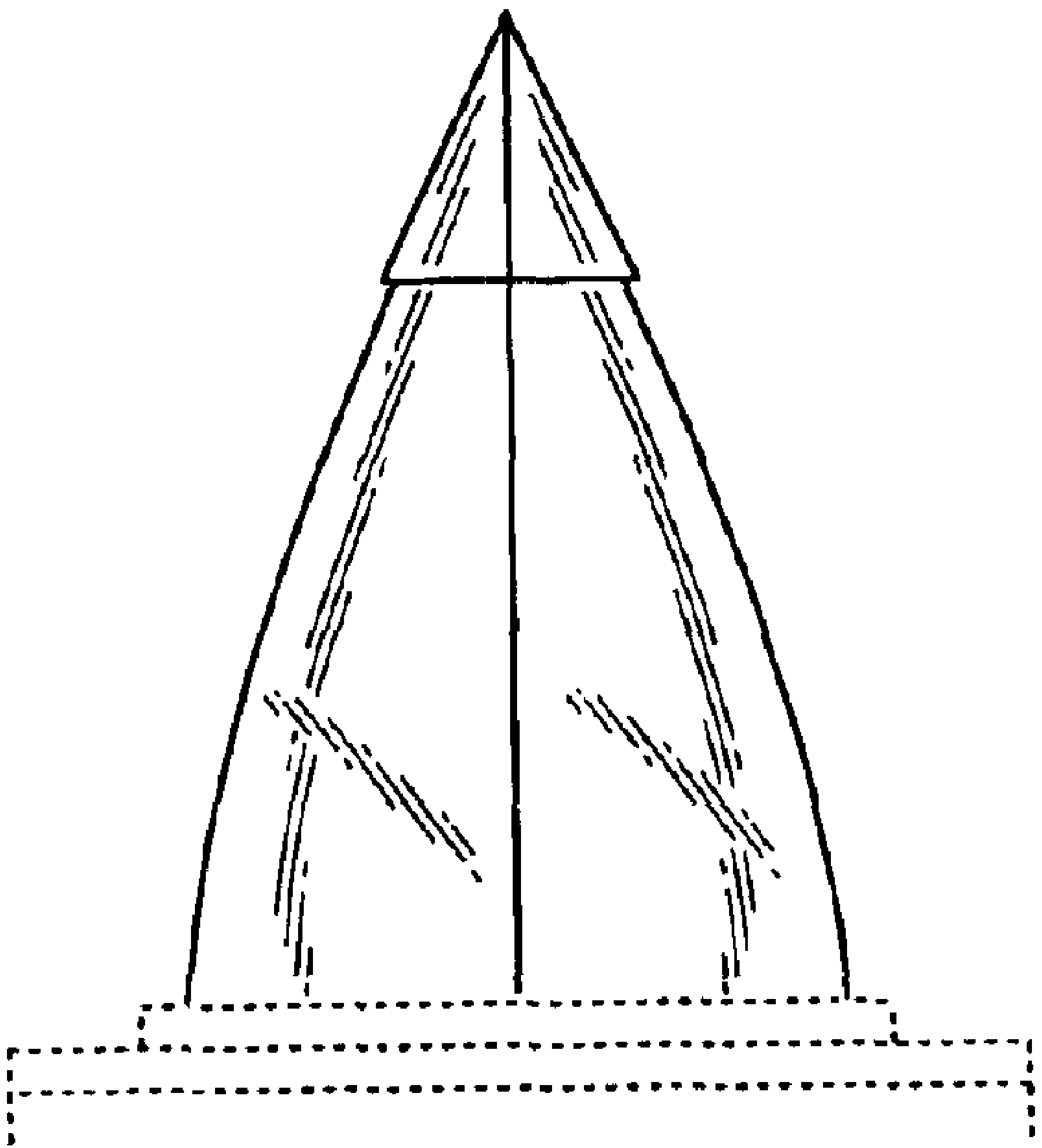

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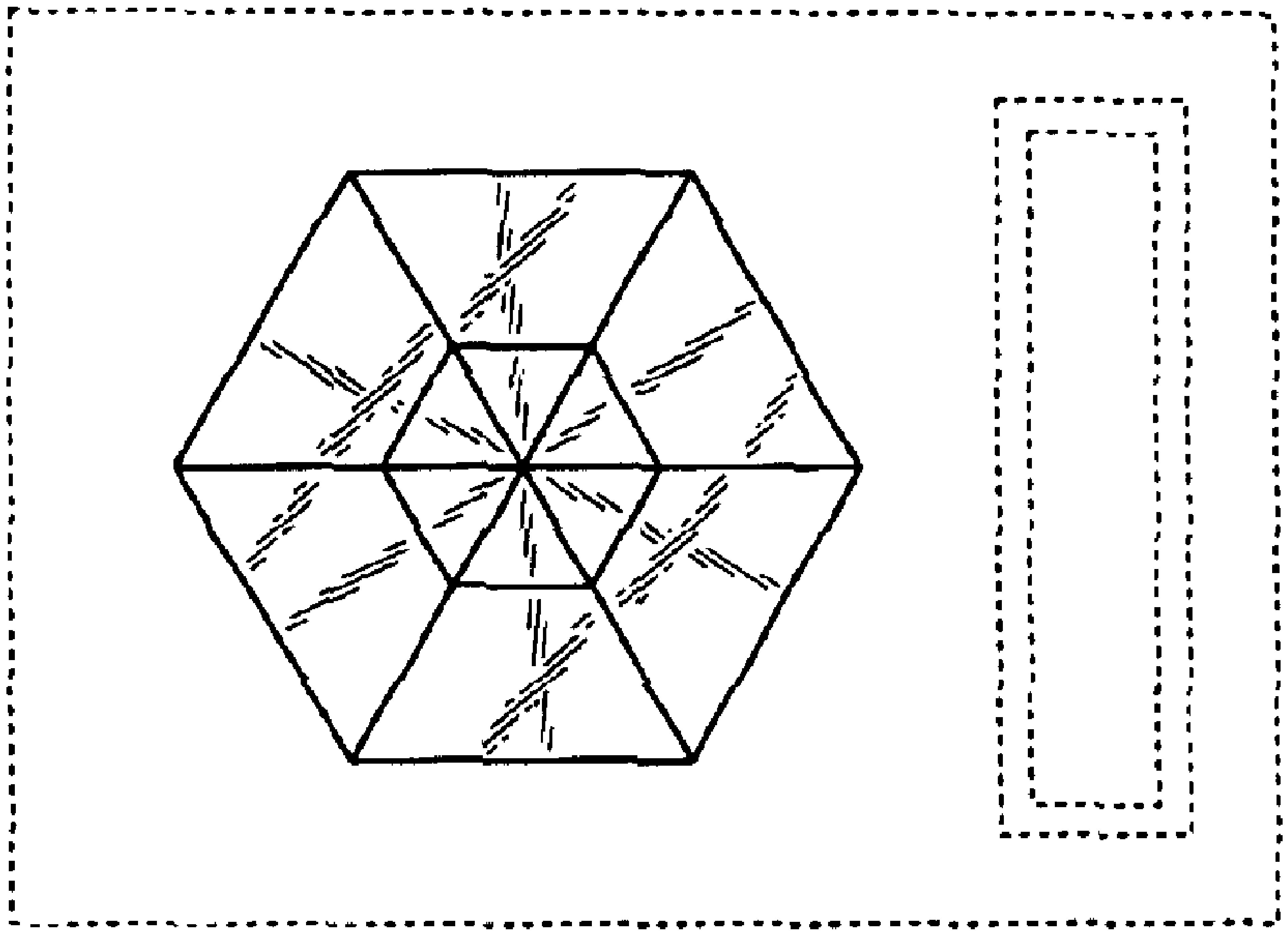

FIG. 36